

Compal Confidential

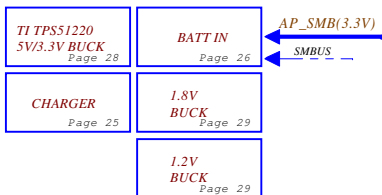
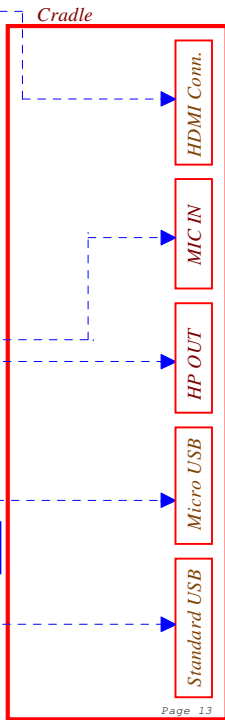
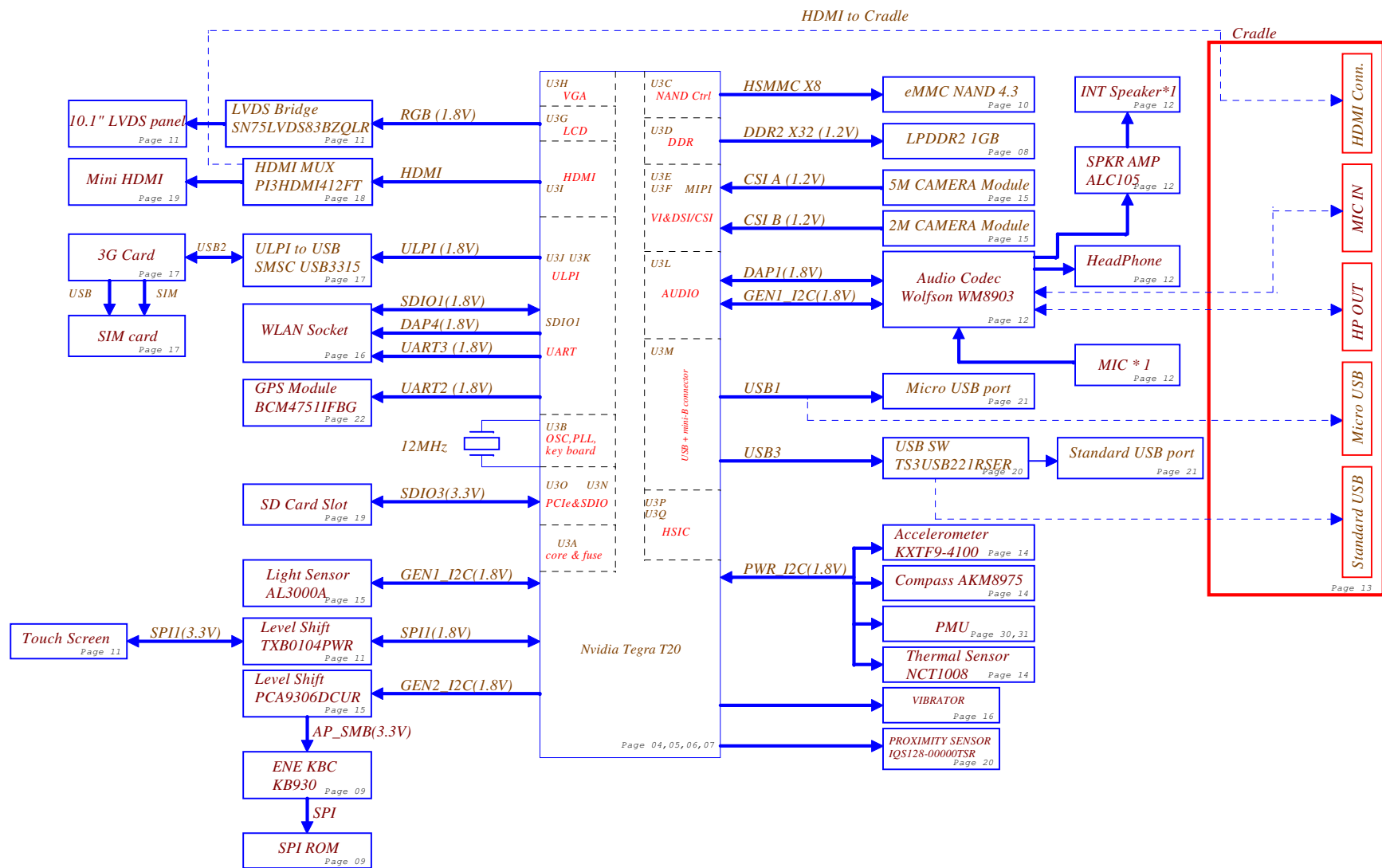
LA-7461 Schematics Document

Nvdia(T20) + LPDDRII

2011-04-22

REV: 0.3

Security Classification		Compal Secret Data		Compal Electronics, Inc.	
Issued Date		Deciphered Date		Title	
2011/4/1		2010/12/01		Cover Page	
THIS SHEET OF ENGINEERING DRAWING IS THE PROPRIETARY PROPERTY OF COMPAL ELECTRONICS, INC. AND CONTAINS CONFIDENTIAL AND TRADE SECRET INFORMATION. THIS SHEET MAY NOT BE TRANSFERRED FROM THE CUSTODY OF THE COMPETENT DIVISION OF R&D DEPARTMENT EXCEPT AS AUTHORIZED BY COMPAL ELECTRONICS, INC. NEITHER THIS SHEET NOR THE INFORMATION IT CONTAINS MAY BE USED BY OR DISCLOSED TO ANY THIRD PARTY WITHOUT PRIOR WRITTEN CONSENT OF COMPAL ELECTRONICS, INC.				Size	Document Number
				Custom	LA-7461P
Date				Monday, April 25, 2011	Sheet 1 of 35
Rev				0.3	



Voltage Rails

Power Plane	Description
VIN	Power supply (19V)
B+	AC or battery power rail for power circuit.
+1.2VS_SM0	Core voltage for CPU
+1.0VS_SM1	CPU voltage for CPU
+1.1VS_LDO1	AVDD_PLL power rail
+1.2VS_LDO2	T20 RTC power rail
+1.8VS_LDO4	T20 system power rail
+3.3VS_LDO3	T20 USB power rail
+2.85VS_LDO5	Core voltage for EMMC
+2.85VS_LDO6	Core voltage for CAMERA
+3.3VS_LDO7	T20 HDMI power rail
+1.8VS_LDO8	T20 HDMI PLL power rail
+2.85VS_LDO9	T20 DDR RX power rail
+3VALW	3.3V always on power rail
+3VS	3.3V switched power rail for standby mode
+5VALW	5V always on power rail
+1.8VS	1.8V always on power rail
+1.8VS_S3	1.8V switched power rail for standby mode
+3.3VS_RTC	RTC power

LPDDR2

NAND_D5	NAND_D4	SMT		LPDDR2		Part Number
L	L	R38	R39	ELPIDA	1G	SA000048Q30
L	H	R23	R39	Hynix	1G	SA00004MJ10
H	L	R38	R24	Samsung	1G	NA
H	H	R23	R24	NA		NA

PWR_I2C address

Device	Address	Device	Address
☐ FMU	0110 100x b	CAMERA 5M	
☐ E-Compass	0000 110x b	CAMERA 2M	
☐ Temperature sensor	0100 110x b		

CAM_I2C address

GEN1_I2C

Device	Address	Device	Address
☐ Audio Codec	0011 010x b		
☐ Light sensor	0001 110x b		

TS_I2C

GEN2_I2C

Device	Address	Device	Address
		LCD	
		3G CARD	

AP_SMB

EC_SMB

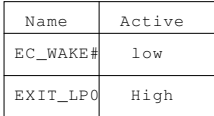
Device	Address	Device	Address
☐ BATT	0001 001x b	☐ G-sensor	0001 1111 b

IME_I2C

DDC_I2C

Device	Address
HDM EDID	

HDMI_DDC_I2C



NAND_D5	NAND_D4	SMT	LPDDR2
L	L	R38,R39	ELPIDA 1G
L	H	R23,R39	Hynix 1G
H	L	R38,R24	NA
H	H	R23,R24	NA

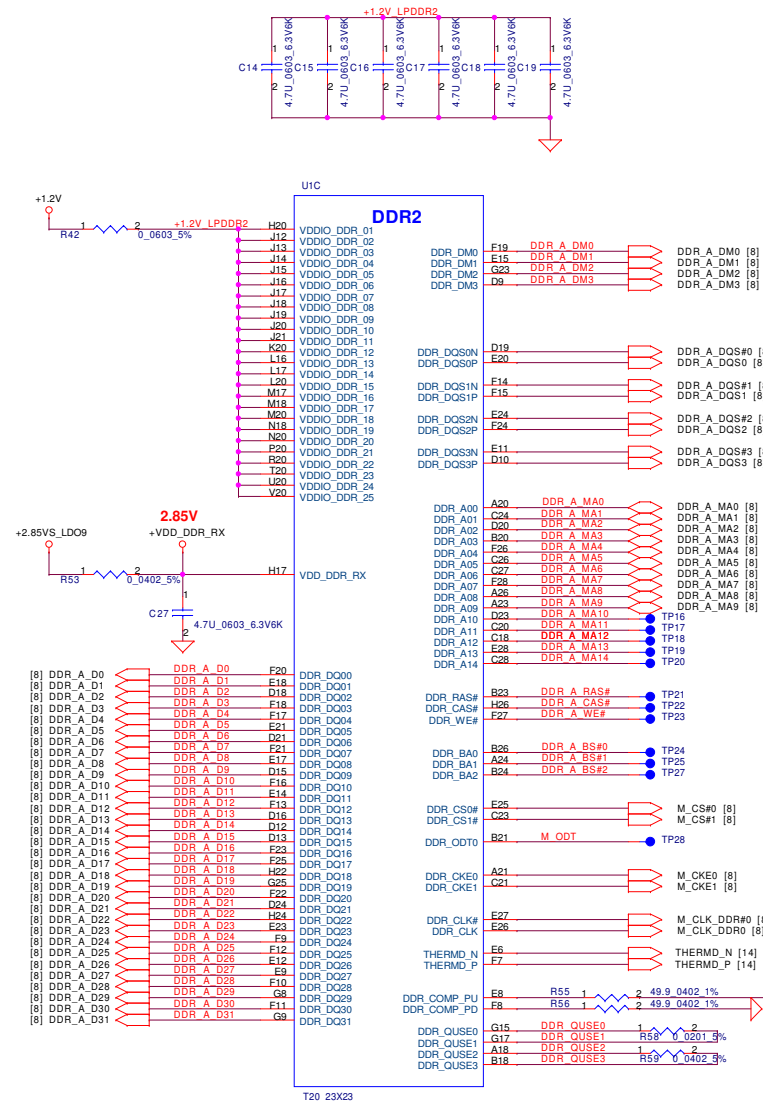
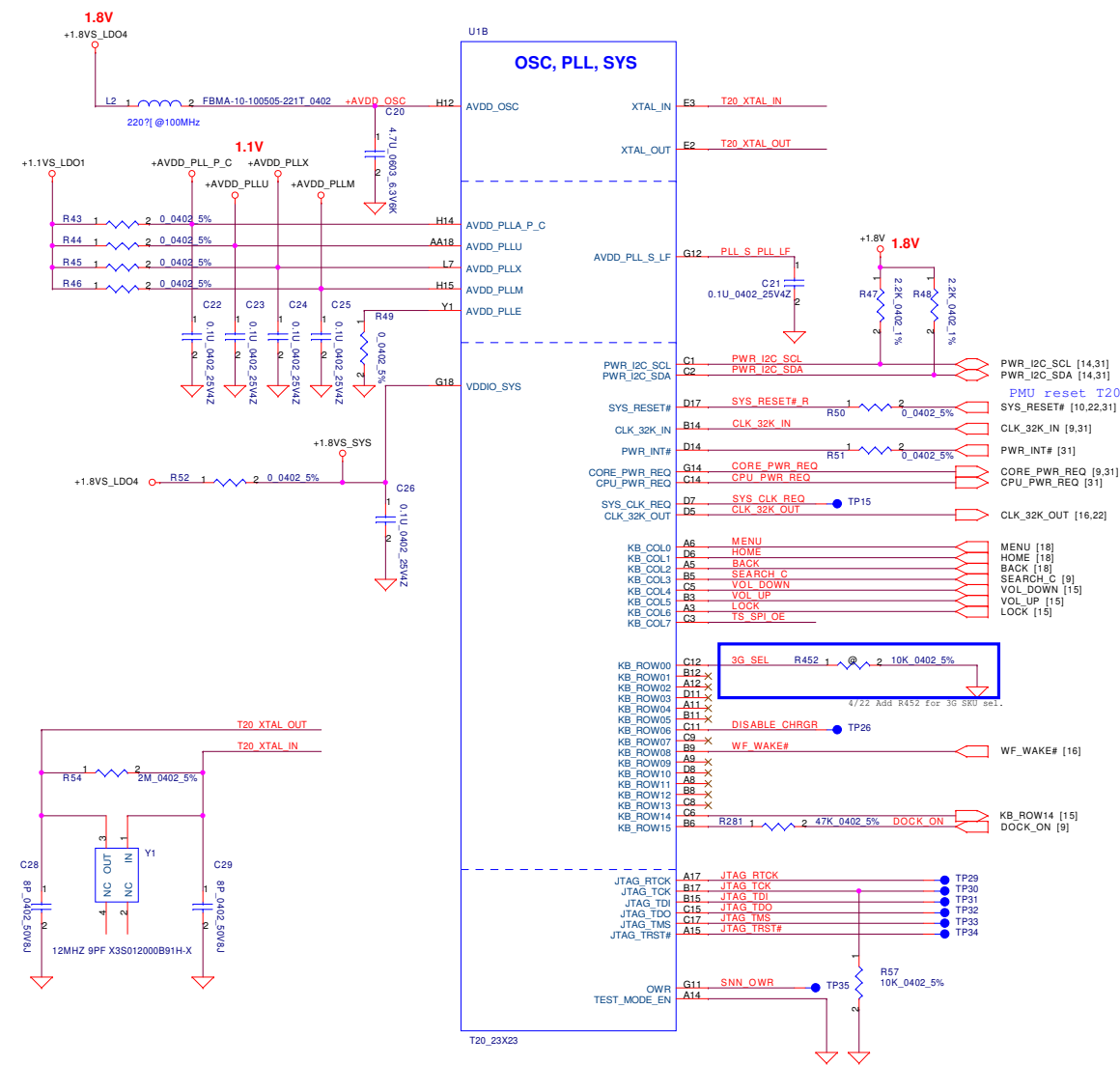
```

eMMC boot
GMI_AD12    1
GMI_AD13    0
GMI_AD14    0
GMI_AD15    0

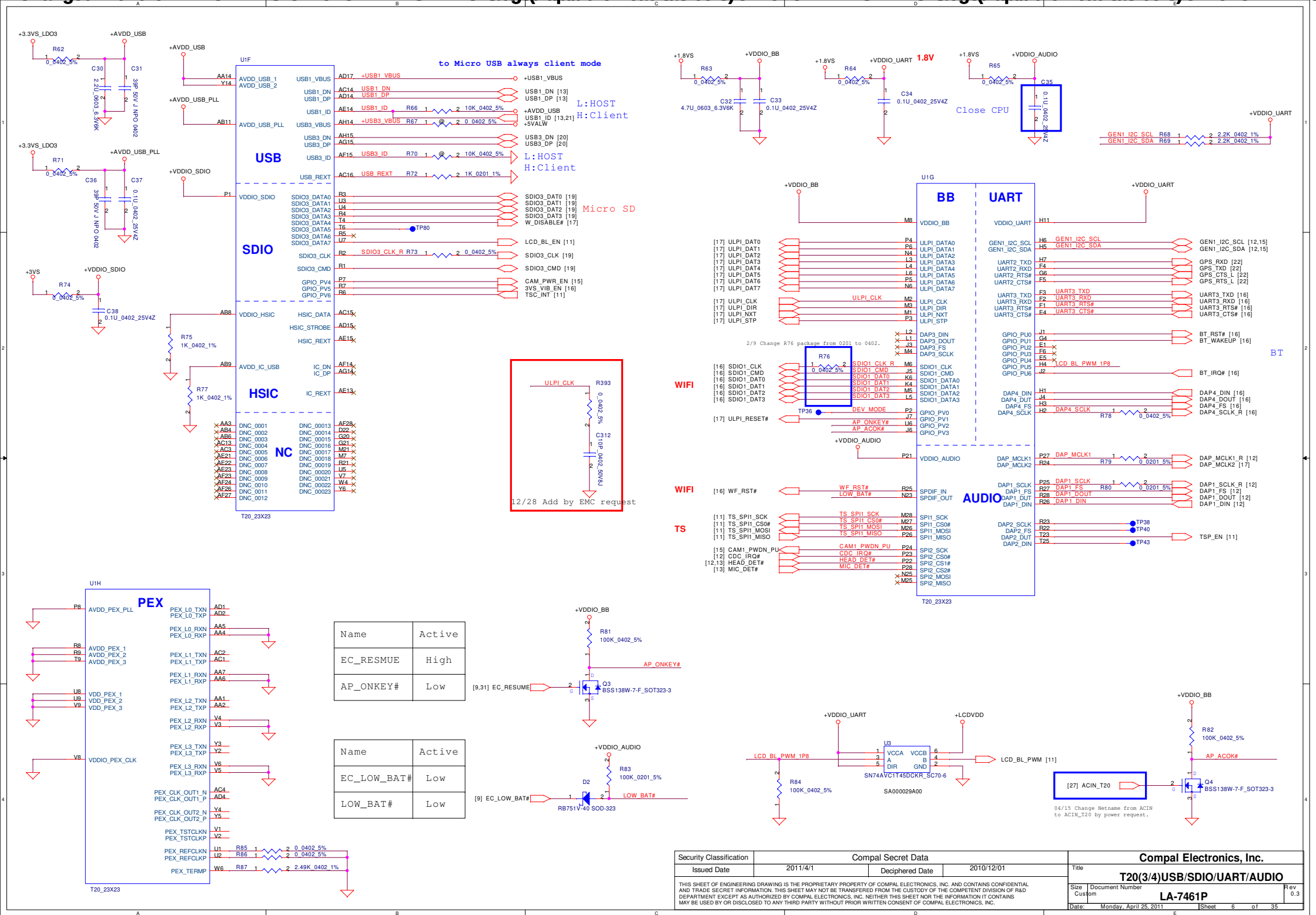
```

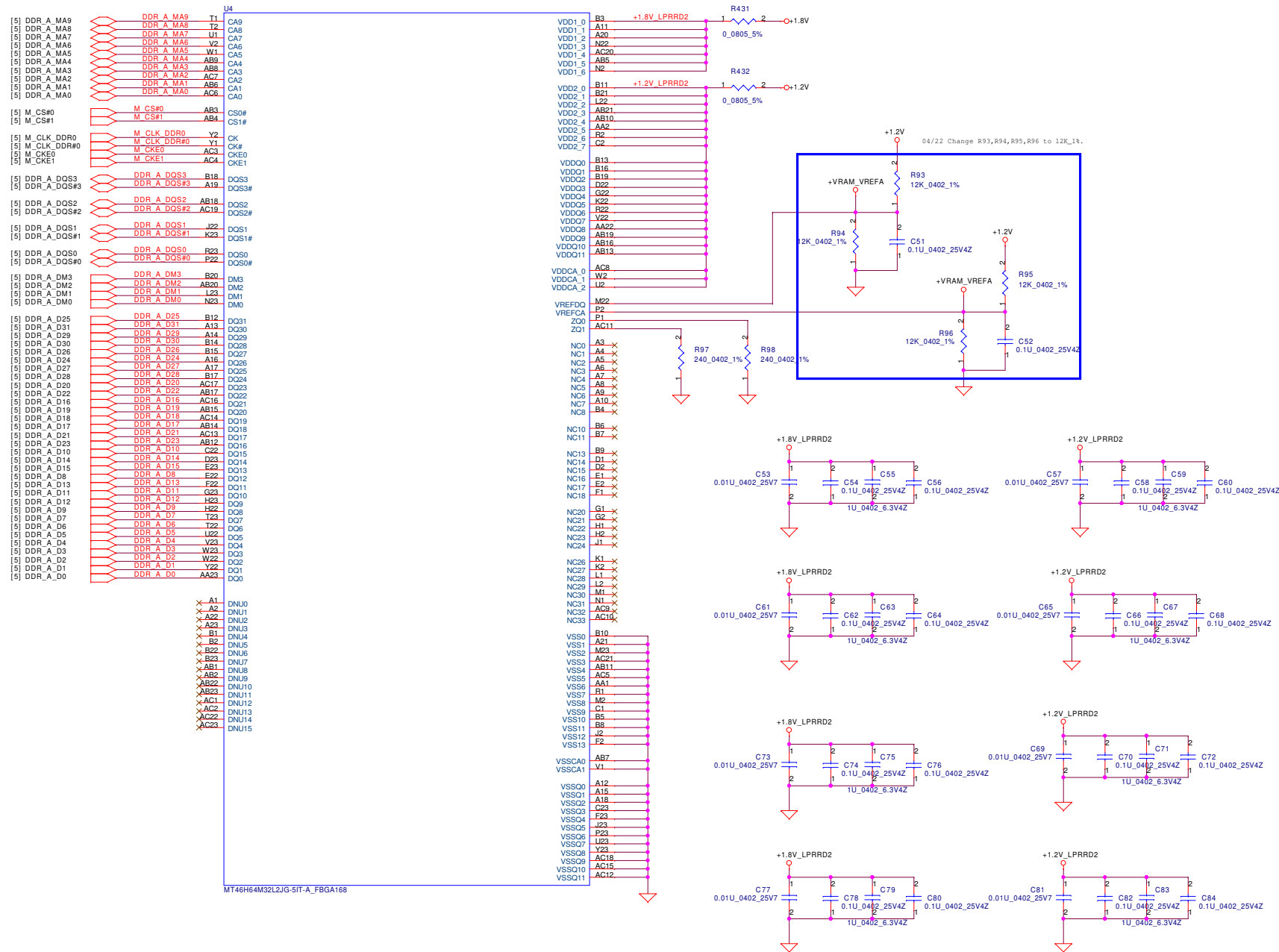
RAM	LPDDR2
NAND_D4	0
NAND_D5	0
NAND_D6	0
NAND_D7	0

Security Classification	Compal Secret Data			Compal Electronics, Inc.			
Issued Date	2011/4/1	Deciphered Date	2010/12/01	Title	T20(1/4)LCD/CRT/HDMI/NAND		
THIS SHEET OF ENGINEERING DRAWING IS THE PROPRIETARY PROPERTY OF COMPAL ELECTRONICS, INC. AND CONTAINS CONFIDENTIAL AND TRADE SECRET INFORMATION. THIS SHEET MAY NOT BE TRANSFERRED FROM THE CUSTODY OF THE COMPETENT DIVISION OF R&D DEPARTMENT EXCEPT AS AUTHORIZED BY COMPAL ELECTRONICS, INC. NEITHER THIS SHEET NOR THE INFORMATION IT CONTAINS MAY BE USED BY OR DISCLOSED TO ANY THIRD PARTY WITHOUT PRIOR WRITTEN CONSENT OF COMPAL ELECTRONICS, INC.				Size	Document Number	Rev	
				Cuspm	LA-7461P	0.3	
				Date:	Monday, April 25, 2011	Sheet 4 of 35	

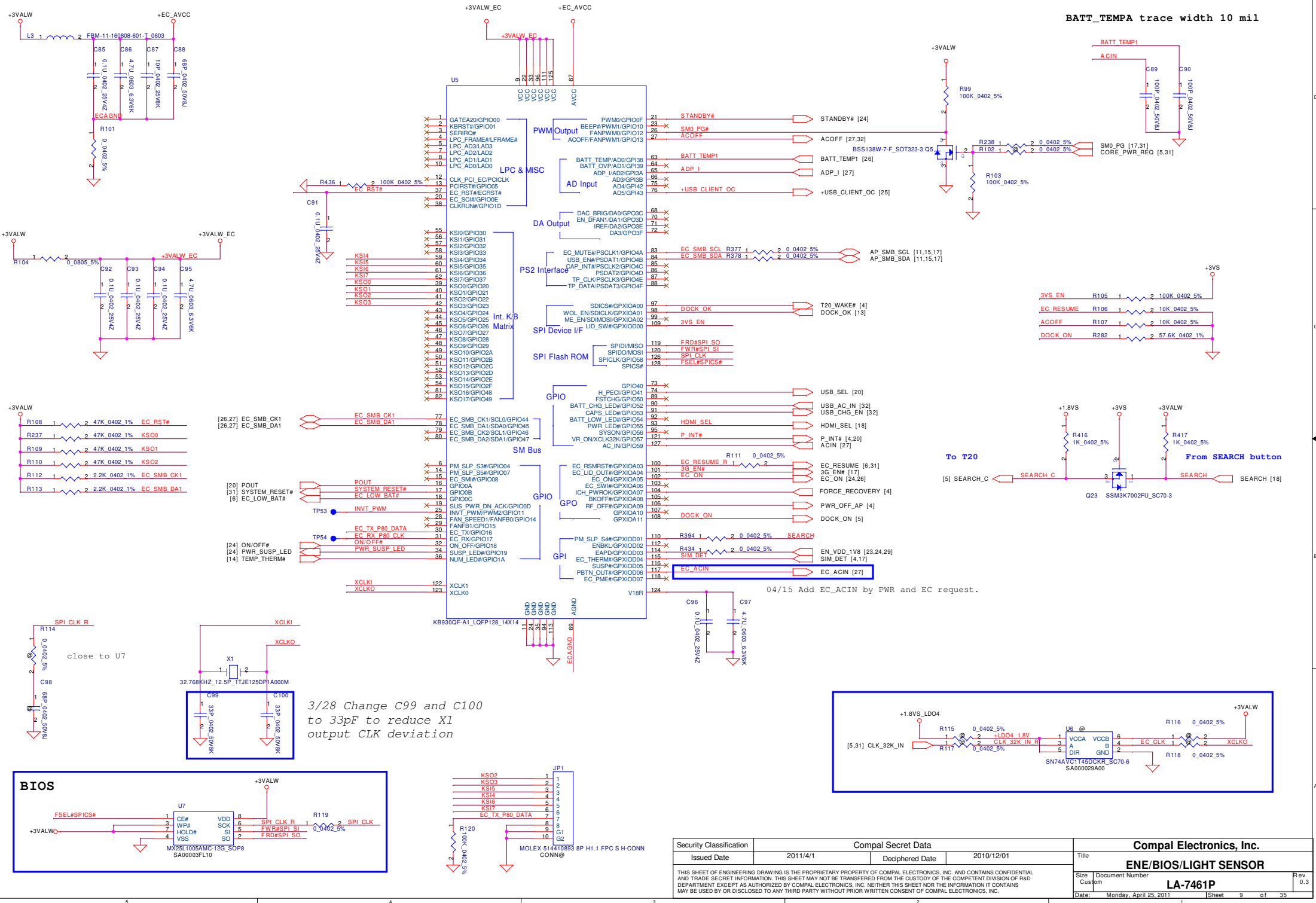


Security Classification		Compal Secret Data		Compal Electronics, Inc.	
Issued Date	2011/4/1	Deciphered Date	2010/12/01	Title	T20(2/4)OSC/PLL/SYS/DDR
THIS SHEET OF ENGINEERING DRAWING IS THE PROPRIETARY PROPERTY OF COMPAL ELECTRONICS, INC. AND CONTAINS CONFIDENTIAL AND TRADE SECRET INFORMATION. THIS SHEET MAY NOT BE TRANSFERRED FROM THE CUSTODY OF THE COMPETENT DIVISION OF R&D DEPARTMENT EXCEPT AS AUTHORIZED BY COMPAL ELECTRONICS, INC. NEITHER THIS SHEET NOR THE INFORMATION IT CONTAINS MAY BE USED BY OR DISCLOSED TO ANY THIRD PARTY WITHOUT PRIOR WRITTEN CONSENT OF COMPAL ELECTRONICS, INC.				Size	Document Number
				Custom	LA-7461P
				Date:	Monday, April 25, 2011
				Sheet	5 of 35





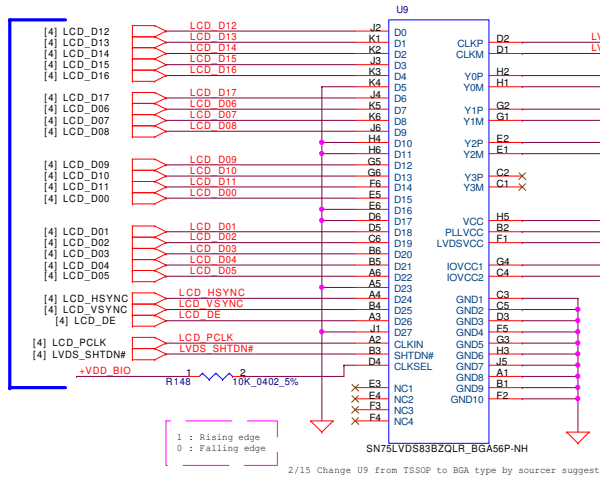
Security Classification		Compal Secret Data		Compal Electronics, Inc.			
Issued Date		2011/4/1	Deciphered Date	2010/12/01	Title		
THIS SHEET OF ENGINEERING DRAWING IS THE PROPRIETARY PROPERTY OF COMPAL ELECTRONICS, INC. AND CONTAINS CONFIDENTIAL AND TRADE SECRET INFORMATION. THIS SHEET MAY NOT BE TRANSFERRED FROM THE CUSTODY OF THE COMPETENT DIVISION OF R&D DEPARTMENT EXCEPT AS AUTHORIZED BY COMPAL ELECTRONICS, INC. NEITHER THIS SHEET NOR THE INFORMATION IT CONTAINS MAY BE USED BY OR DISCLOSED TO ANY THIRD PARTY WITHOUT PRIOR WRITTEN CONSENT OF COMPAL ELECTRONICS, INC.					DDRII-DEVICE DOWN(1/2)		
					Size	Document Number	Rev
					Custom	LA-7461P	0.3
					Date:	Monday, April 25, 2011	Sheet 8 of 35



Security Classification		Compal Secret Data		Compal Electronics, Inc.	
Issued Date	2011/4/1	Deciphered Date	2010/12/01	Title	
				ENE/BIOS/LIGHT SENSOR	
				Size	Document Number
				Custom	LA-7461P
				Date	Monday, April 25, 2011
				Sheet	9 of 35

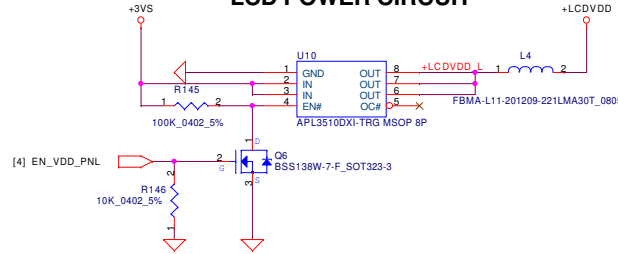
LVDS Bridge

1.8V level

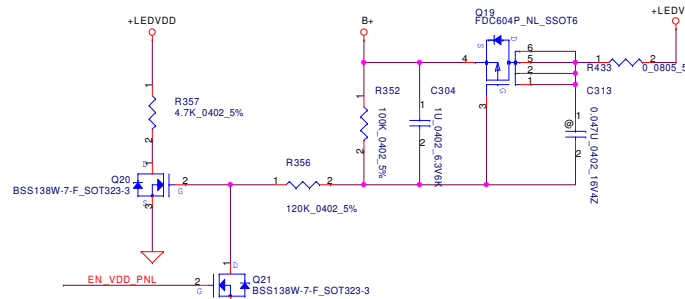


LVDS

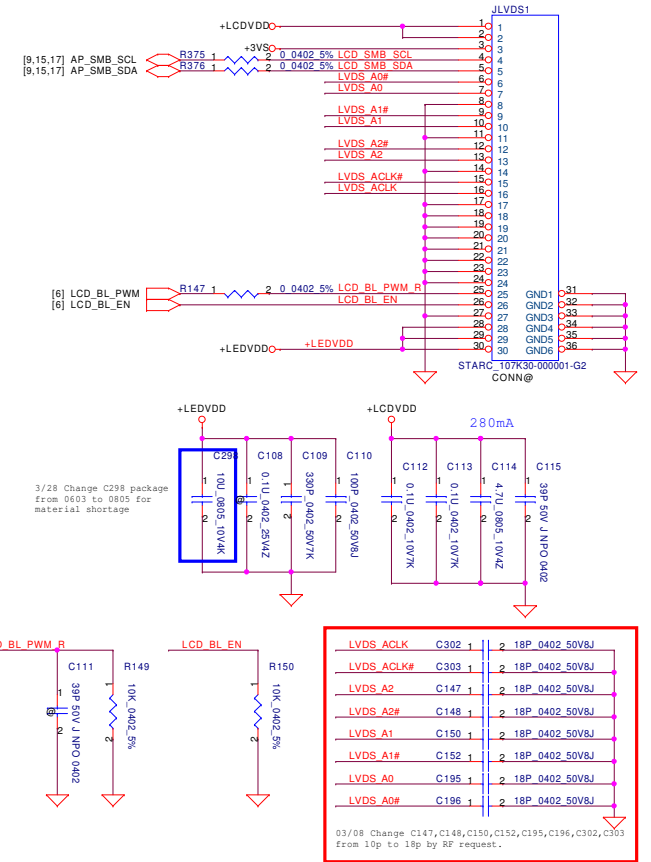
LCD POWER CIRCUIT



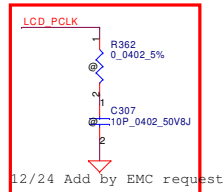
LED POWER CIRCUIT



LVDS CONN



Close U9

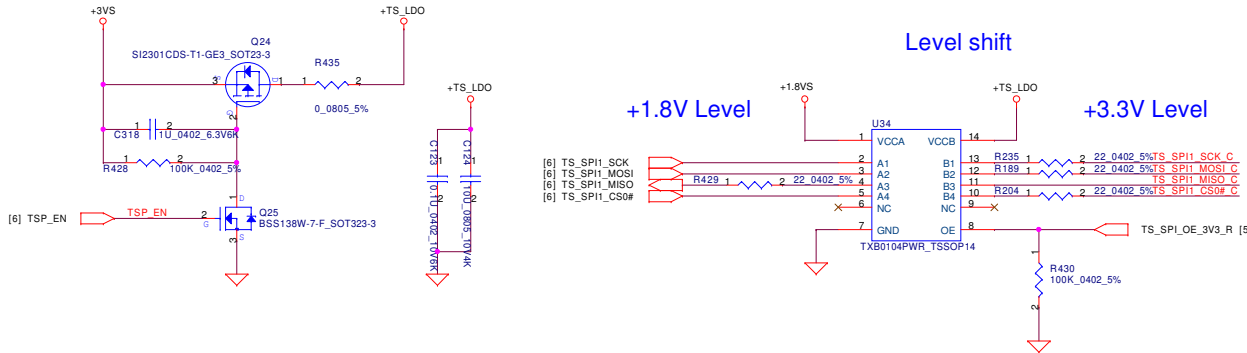


TOUCH SCREEN

Level shift

+1.8V Level

+3.3V Level

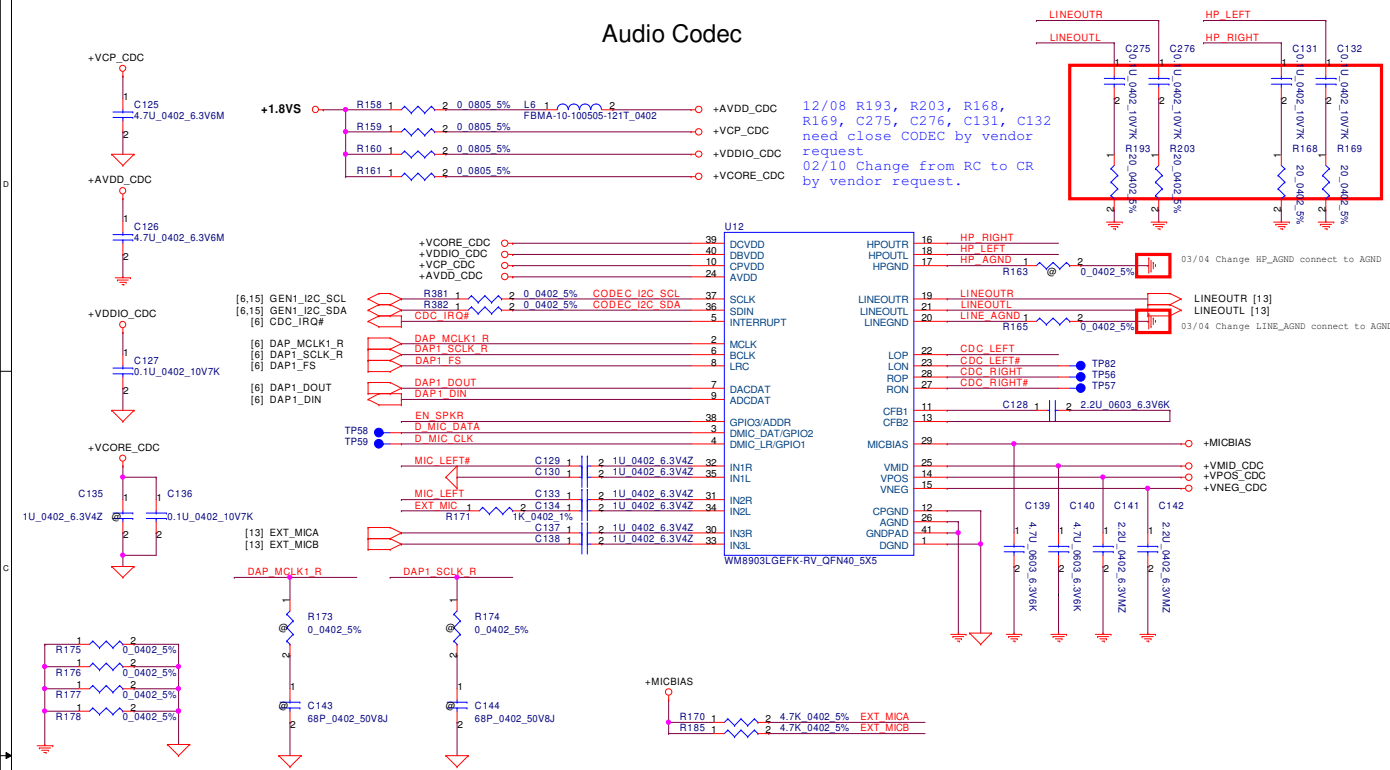


3/22 Swap JTS1 pin2 and pin3 to follow module pin define.

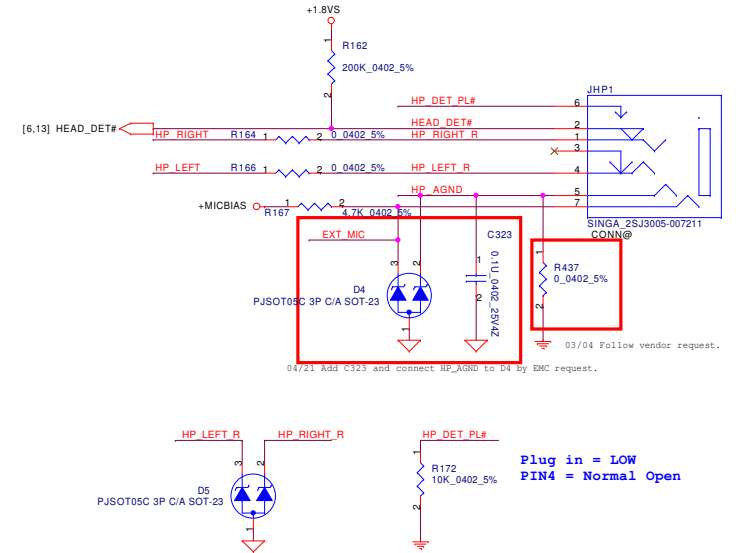
Pin #	SPI interface (Compal XPAD) Host side 10 pins-Proposed
1	CGND
2	MISO
3	MOSI
4	INT#
5	SCK
6	GND
7	N.C
8	LDO (Low Dropout Regulator) +3.3 Vcc
9	CS0#
10	SS_L, Slave Select (active low)

Security Classification	Compal Secret Data	Title	Compal Electronics, Inc.
Issued Date	2011/4/1	Deciphered Date	2010/12/01
THIS SHEET OF ENGINEERING DRAWING IS THE PROPRIETARY PROPERTY OF COMPAL ELECTRONICS, INC. AND CONTAINS CONFIDENTIAL AND TRADE SECRET INFORMATION. THIS SHEET MAY NOT BE TRANSFERRED FROM THE CUSTODY OF THE COMPETENT DIVISION OF R&D DEPARTMENT EXCEPT AS AUTHORIZED BY COMPAL ELECTRONICS, INC. NEITHER THIS SHEET NOR THE INFORMATION IT CONTAINS MAY BE USED BY OR DISCLOSED TO ANY THIRD PARTY WITHOUT PRIOR WRITTEN CONSENT OF COMPAL ELECTRONICS, INC.			
Size	Document Number	Rev	0.3
Custom	LA-7461P		
Date	Monday, April 25, 2011	Sheet	11 of 35

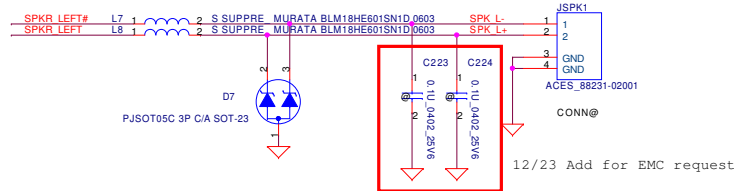
Audio Codec



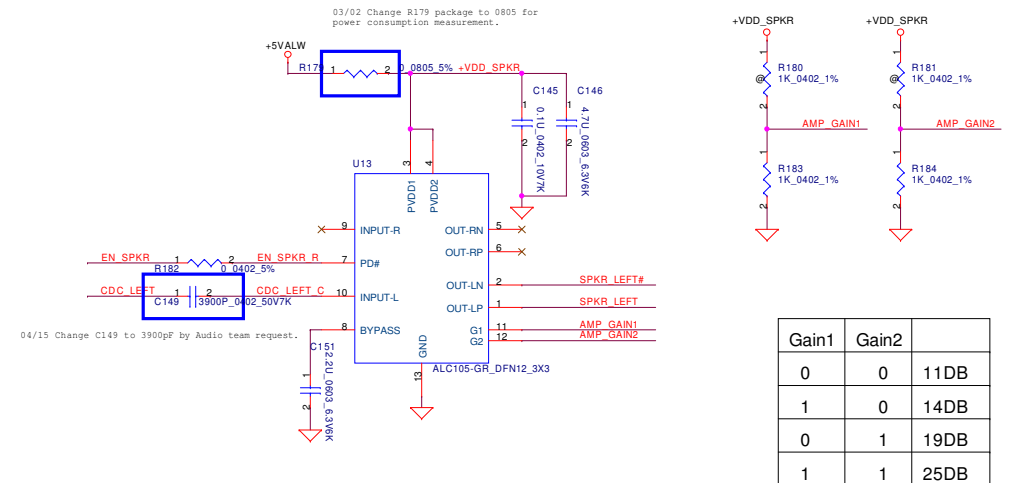
HP Jack



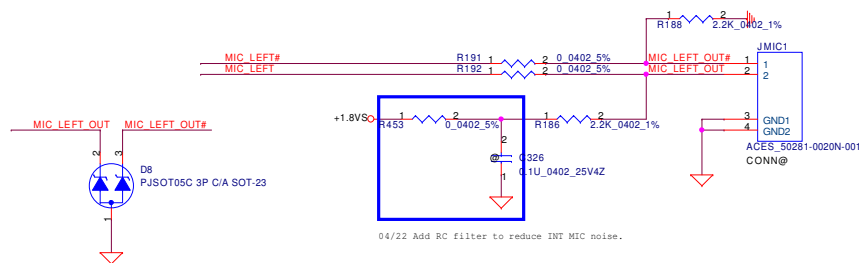
INT. Speaker Conn.



SPK AMP

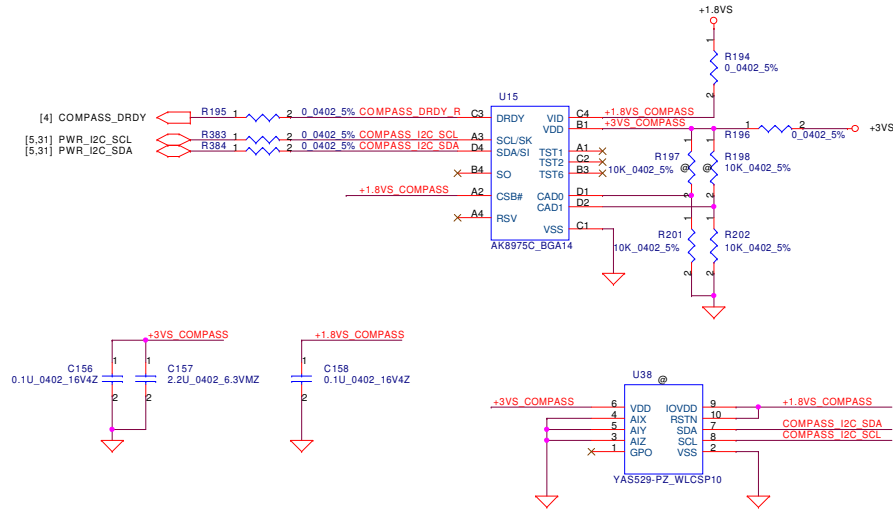


INT. MIC

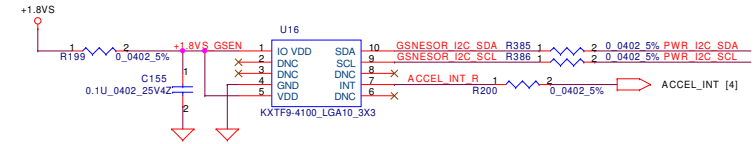


Security Classification		Compal Secret Data		Compal Electronics, Inc.	
Issued Date	2011/4/1	Deciphered Date	2010/12/01	Title	AUDIO CODEC/SPK/JACK/MIC
THIS SHEET OF ENGINEERING DRAWING IS THE PROPRIETARY PROPERTY OF COMPAL ELECTRONICS, INC. AND CONTAINS CONFIDENTIAL AND TRADE SECRET INFORMATION. THIS SHEET MAY NOT BE TRANSFERRED FROM THE CUSTODY OF THE COMPETENT DIVISION OF R&D DEPARTMENT EXCEPT AS AUTHORIZED BY COMPAL ELECTRONICS, INC. NEITHER THIS SHEET NOR THE INFORMATION IT CONTAINS MAY BE USED BY OR DISCLOSED TO ANY THIRD PARTY WITHOUT PRIOR WRITTEN CONSENT OF COMPAL ELECTRONICS, INC.				Size Custom	Document Number LA-7461P
				Date:	Monday, April 25, 2011
				Sheet	12 of 35
				Rev	0.3

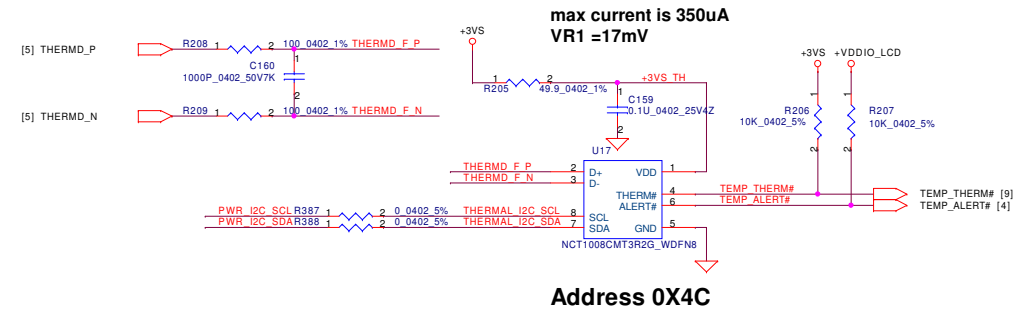
ECompass



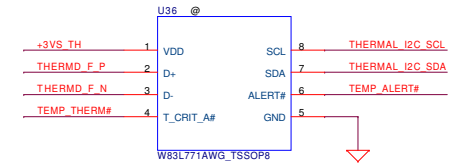
G-SENSOR



THERMAL

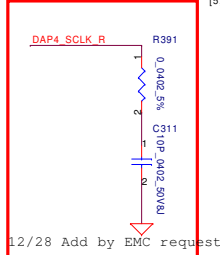
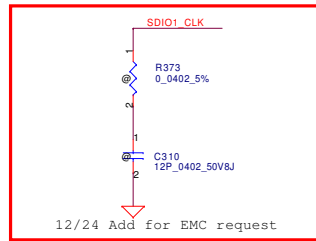
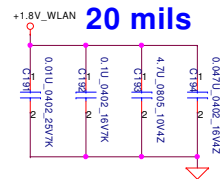
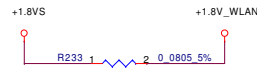
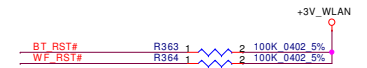


Address 0X4C



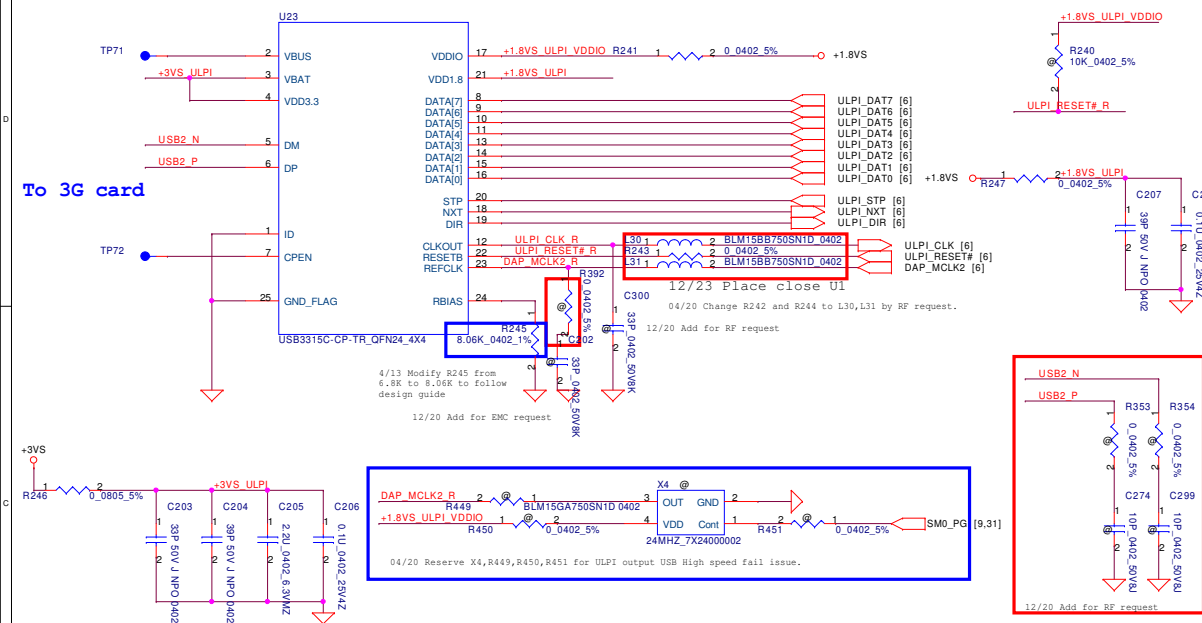
03/01 Reserve thermal sensor for sourcer request

Security Classification		Compal Secret Data		Compal Electronics, Inc.	
Issued Date	2011/4/1	Deciphered Date	2010/12/01	Title	G-SENSOR/ECOMPASS/THERMAL
THIS SHEET OF ENGINEERING DRAWING IS THE PROPRIETARY PROPERTY OF COMPAL ELECTRONICS, INC. AND CONTAINS CONFIDENTIAL AND TRADE SECRET INFORMATION. THIS SHEET MAY NOT BE TRANSFERRED FROM THE CUSTODY OF THE COMPETENT DIVISION OF R&D DEPARTMENT EXCEPT AS AUTHORIZED BY COMPAL ELECTRONICS, INC. NEITHER THIS SHEET NOR THE INFORMATION IT CONTAINS MAY BE USED BY OR DISCLOSED TO ANY THIRD PARTY WITHOUT PRIOR WRITTEN CONSENT OF COMPAL ELECTRONICS, INC.				Size / Document Number	Custom / LA-7461P
				Date	Monday, April 25, 2011
				Sheet	14 of 35
				Rev	0.3

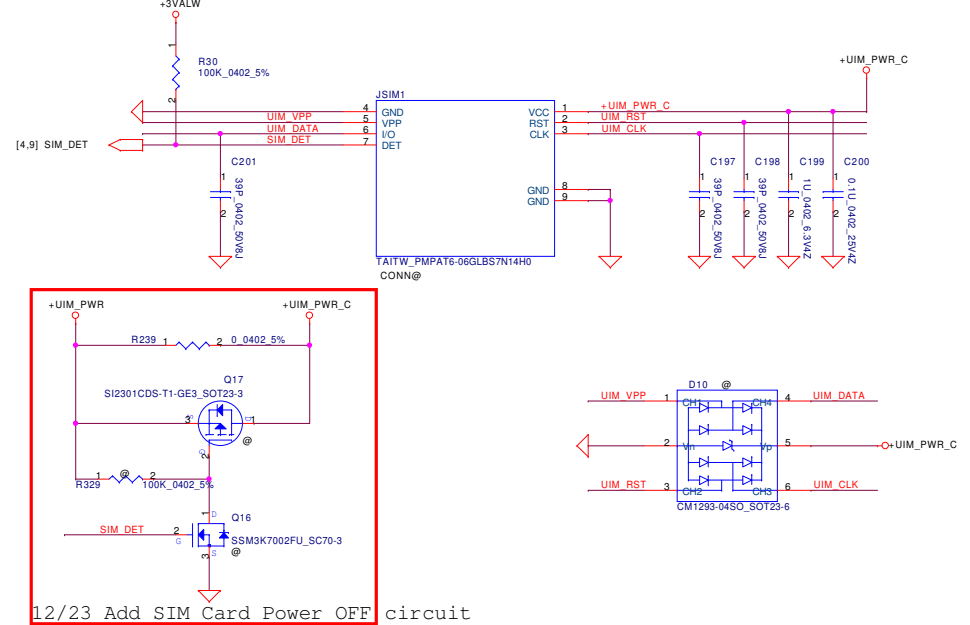
[illegible]

Security Classification		Compal Secret Data		Compal Electronics, Inc.	
Issued Date	2011/4/1	Deciphered Date	2010/12/01	Title	WiFi/BT/LIGHT SENSOR/VIBRATOR
THIS SHEET OF ENGINEERING DRAWING IS THE PROPRIETARY PROPERTY OF COMPAL ELECTRONICS, INC. AND CONTAINS CONFIDENTIAL AND TRADE SECRET INFORMATION. THIS SHEET MAY NOT BE TRANSFERRED FROM THE CUSTODY OF THE COMPETENT DIVISION OF R&D DEPARTMENT EXCEPT AS AUTHORIZED BY COMPAL ELECTRONICS, INC. NEITHER THIS SHEET NOR THE INFORMATION IT CONTAINS MAY BE USED BY OR DISCLOSED TO ANY THIRD PARTY WITHOUT PRIOR WRITTEN CONSENT OF COMPAL ELECTRONICS, INC.				Size	Rev
				Document Number LA-7461P	0.3
Date:		Monday, April 25, 2011		Sheet	16 of 35

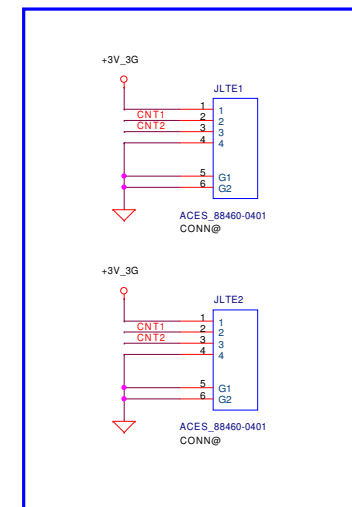
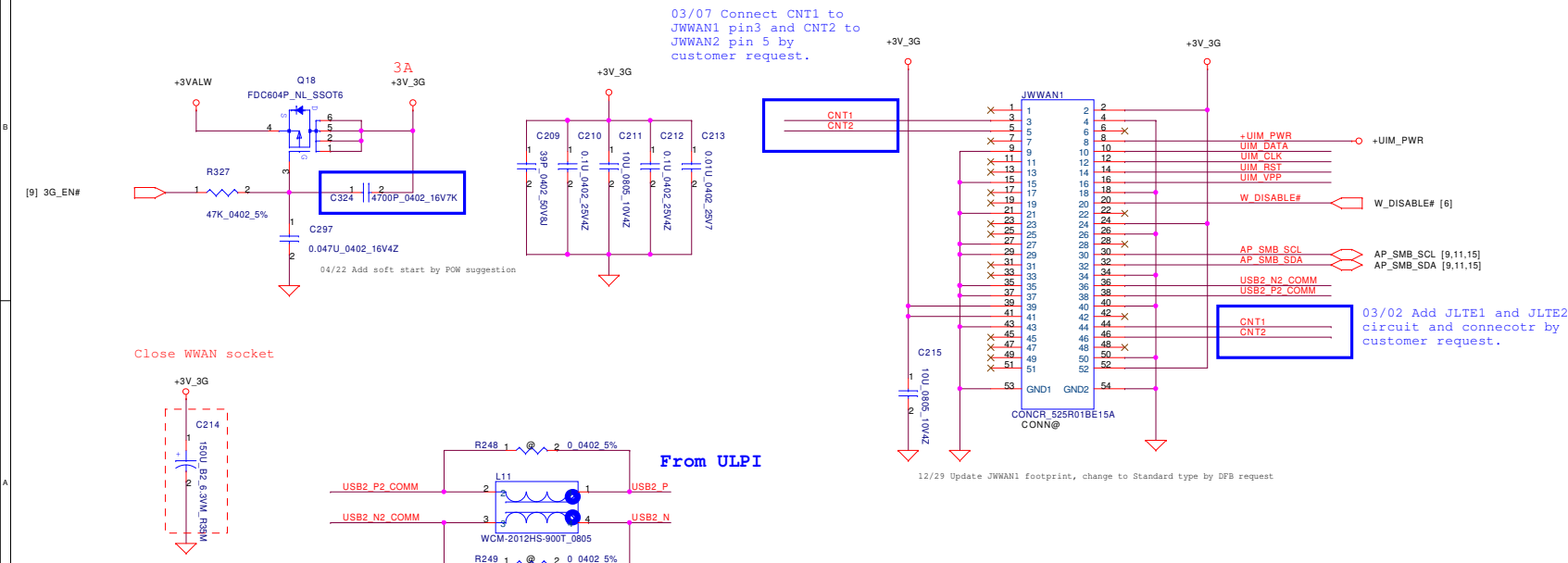
To 3G card



[4,9] SIM_DET

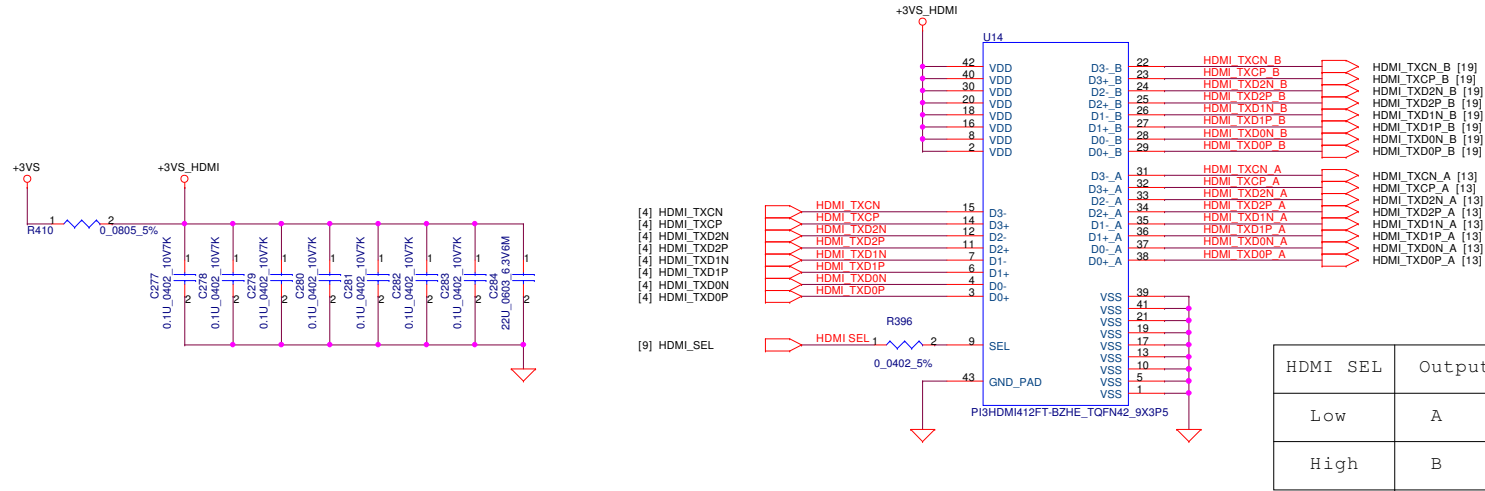


03/07 Connect CNT1 to
JWWAN1 pin3 and CNT2
JWWAN2 pin 5 by
customer request.

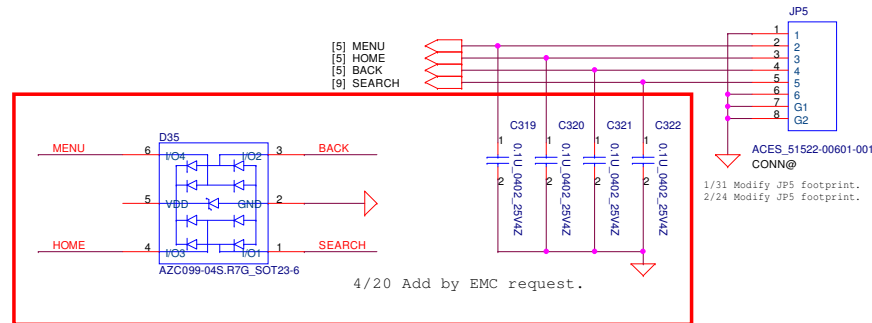


Security Classification		Compal Secret Data		Compal Electronics, Inc.	
Issued Date	2011/4/1	Deciphered Date	2010/12/01	Title	ULPI/3G CARD/SIM CARD
THIS SHEET OF ENGINEERING DRAWING IS THE PROPRIETARY PROPERTY OF COMPAL ELECTRONICS, INC. AND CONTAINS CONFIDENTIAL AND TRADE SECRET INFORMATION. THIS SHEET MAY NOT BE TRANSFERRED FROM THE CUSTODY OF THE COMPETENT DIVISION OF R&D DEPARTMENT EXCEPT AS AUTHORIZED BY COMPAL ELECTRONICS, INC. NEITHER THIS SHEET NOR THE INFORMATION IT CONTAINS MAY BE USED BY OR DISCLOSED TO ANY THIRD PARTY WITHOUT PRIOR WRITTEN CONSENT OF COMPAL ELECTRONICS, INC.				Size	Document Number
				LA-7461P	
Date:		Monday, April 25, 2011		Sheet	17 of 35

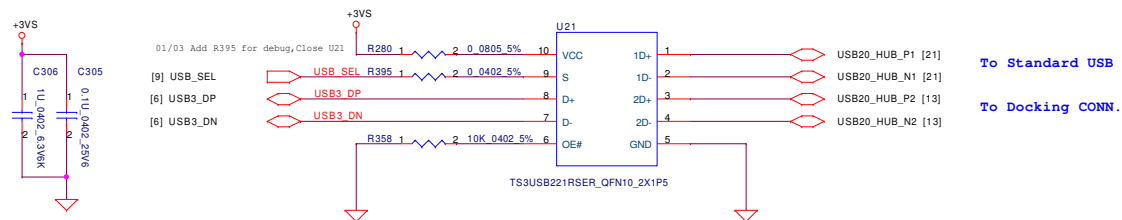
HDMI MUX



Button Board

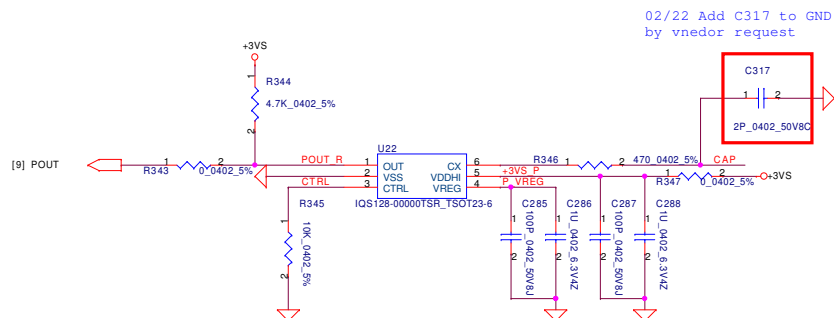


USB SW

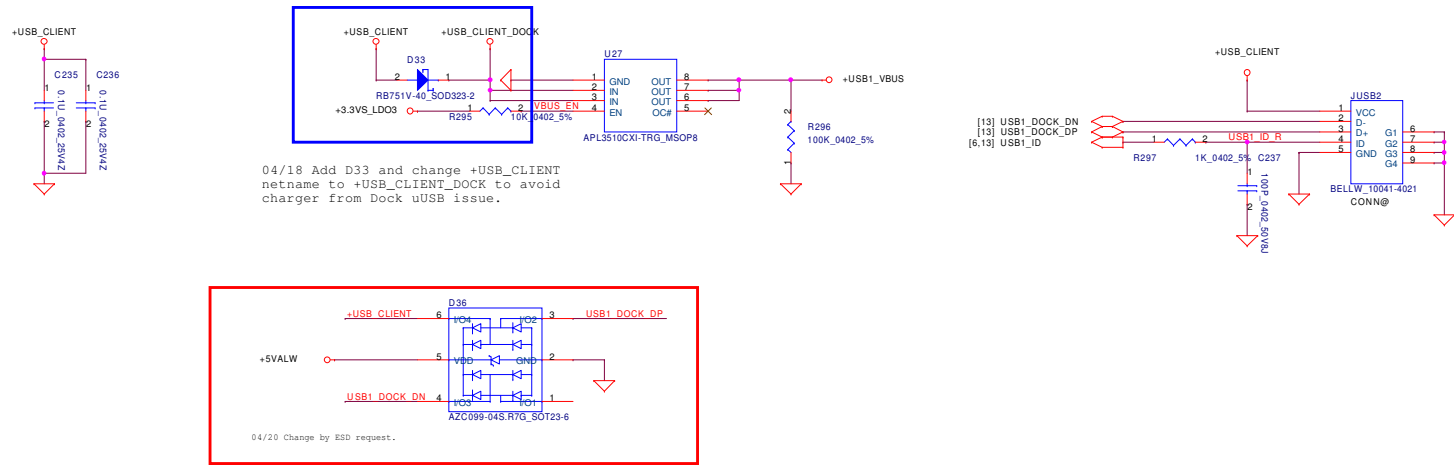


S	Output
L	D = 1D
H	D = 2D

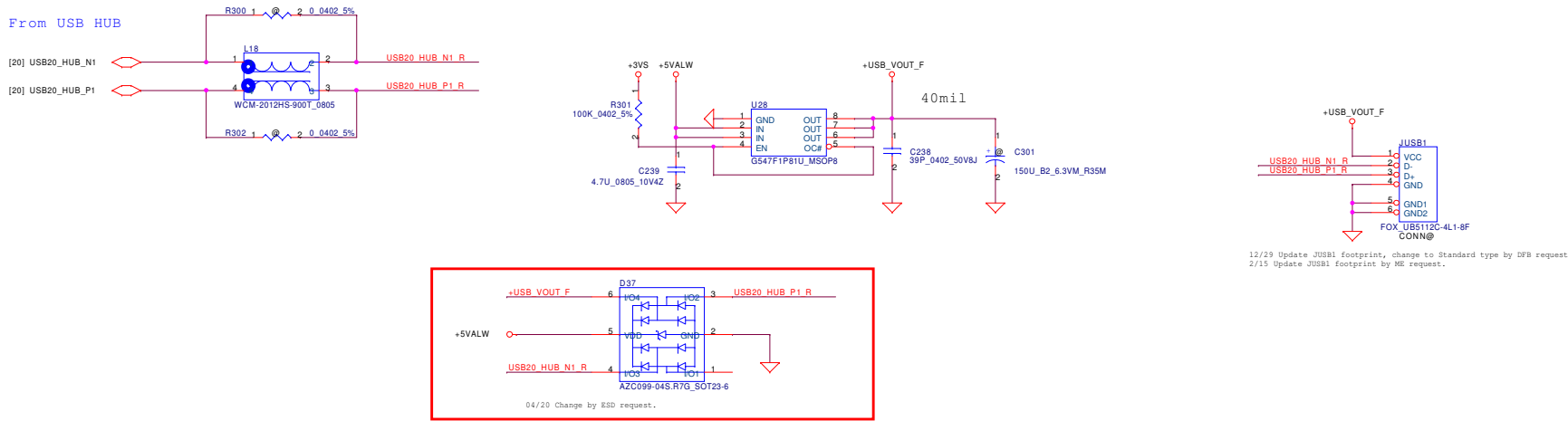
PROXIMITY SENSOR



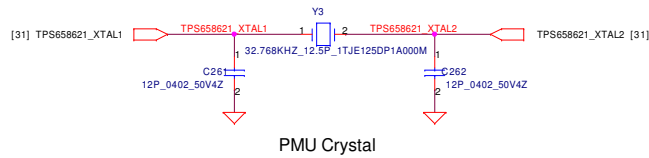
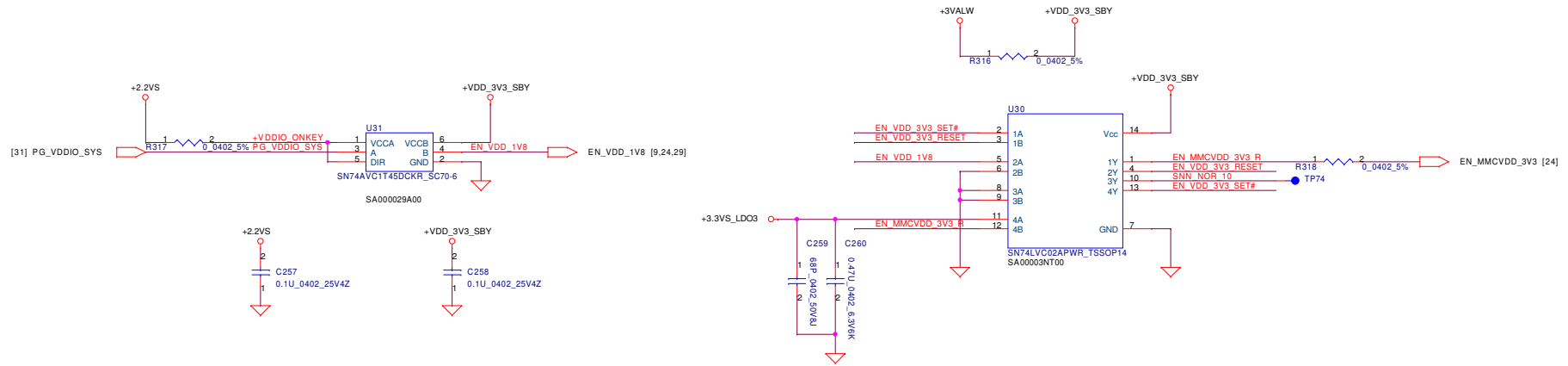
MICRO USB



STANDARD USB

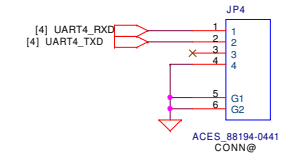


Power Sequence Logic



PMU Crystal

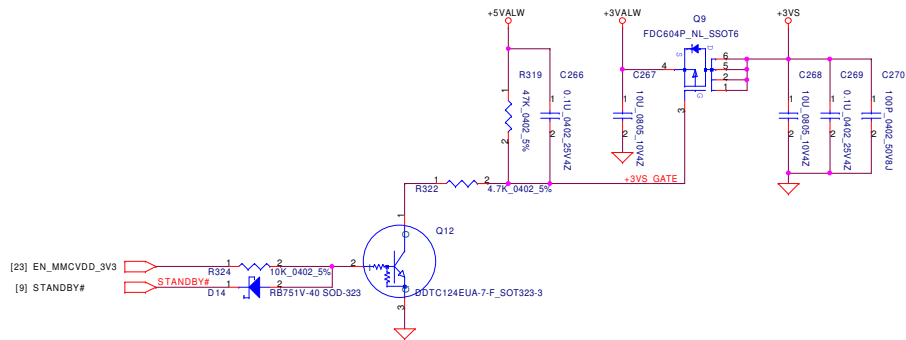
Debug connector



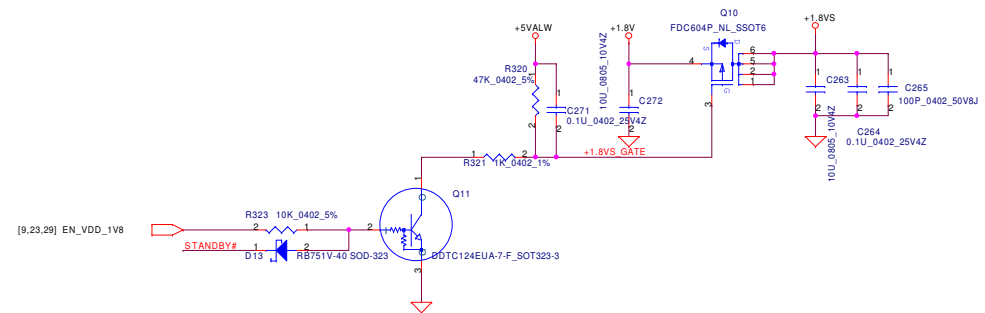
12/16 Add Debug Connector

Security Classification		Compal Secret Data		Compal Electronics, Inc.	
Issued Date	2011/4/1	Deciphered Date	2010/12/01	Title	SEQUENCE/DEBUG
THIS SHEET OF ENGINEERING DRAWING IS THE PROPRIETARY PROPERTY OF COMPAL ELECTRONICS, INC. AND CONTAINS CONFIDENTIAL AND TRADE SECRET INFORMATION. THIS SHEET MAY NOT BE TRANSFERRED FROM THE CUSTODY OF THE COMPETENT DIVISION OF R&D DEPARTMENT EXCEPT AS AUTHORIZED BY COMPAL ELECTRONICS, INC. NEITHER THIS SHEET NOR THE INFORMATION IT CONTAINS MAY BE USED BY OR DISCLOSED TO ANY THIRD PARTY WITHOUT PRIOR WRITTEN CONSENT OF COMPAL ELECTRONICS, INC.				Size Document Number	LA-7461P
				Rev	0.3
				Date	Monday, April 25, 2011
				Sheet	23 of 35

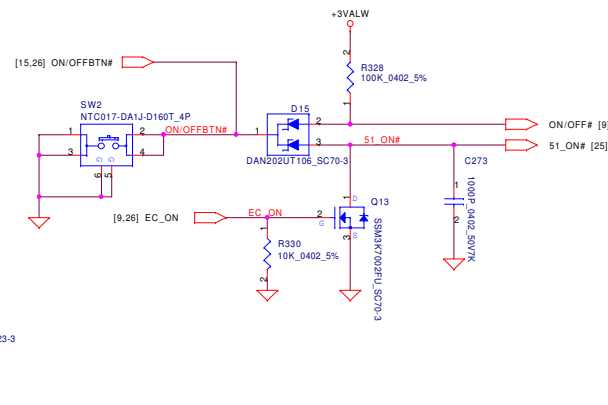
+3VALW to +3VS Transfer



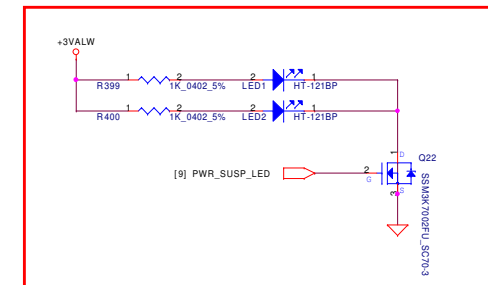
+1.8V to +1.8VS Transfer



Power Button

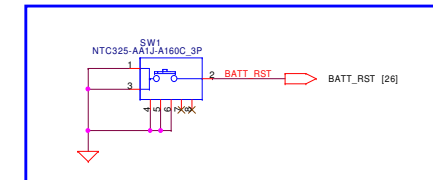


LED

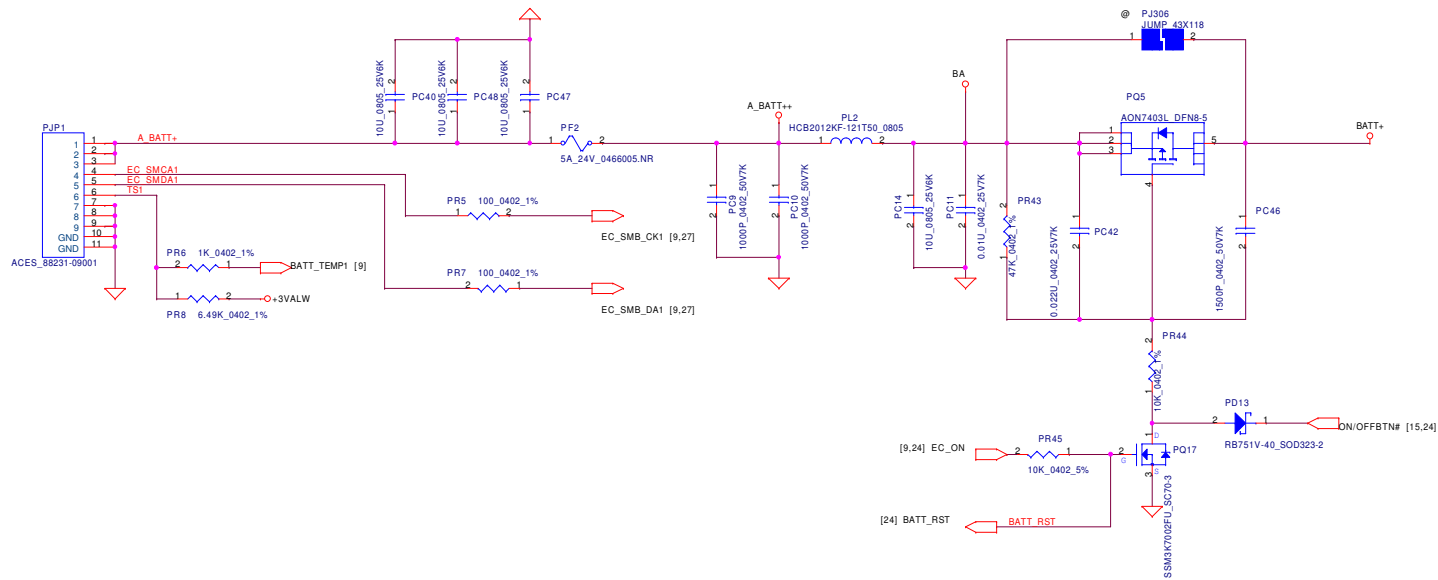


2/9 Add LED for customer request.
4/20 Change LED1 and LED2 from Red light to White light.

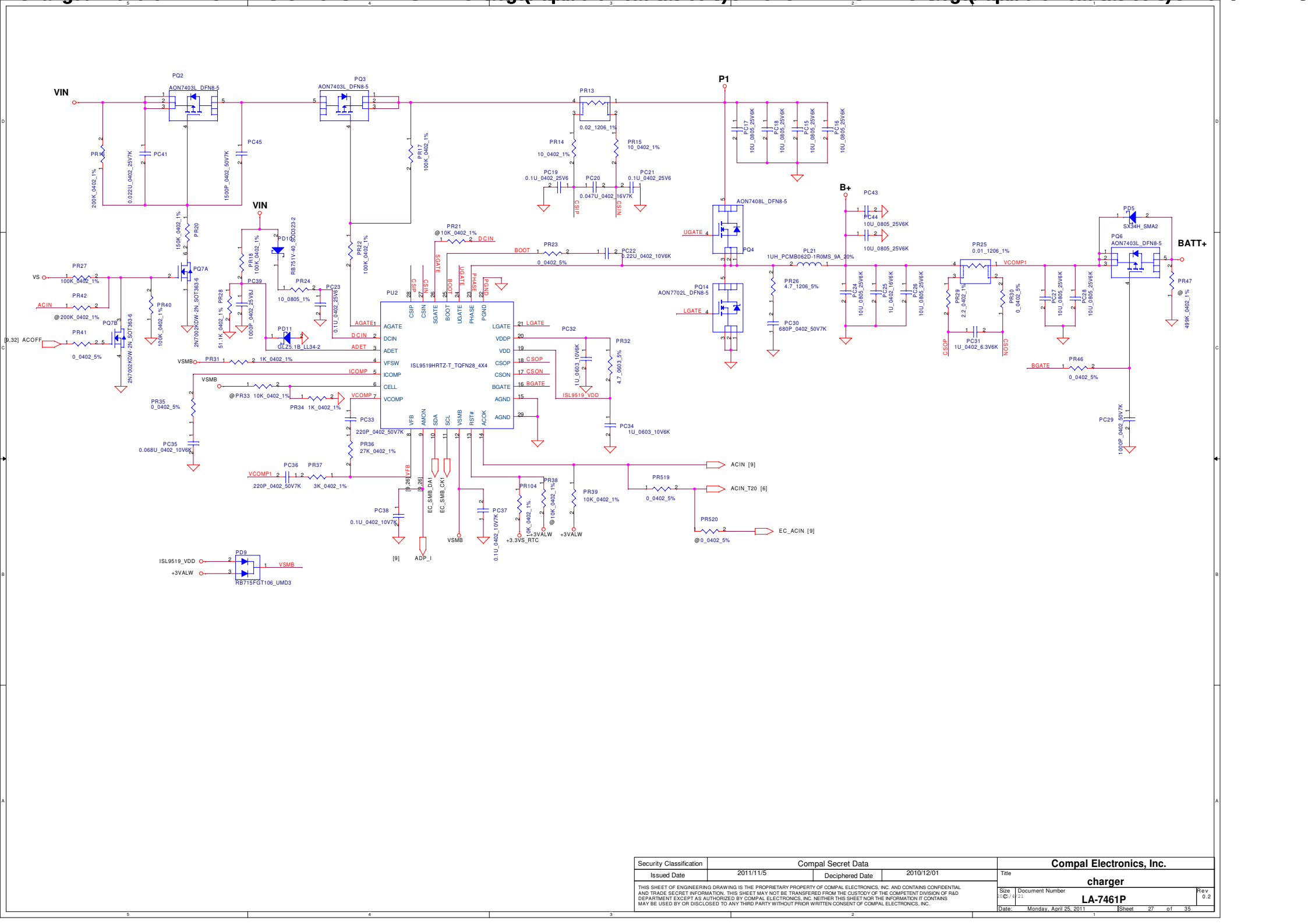
4/15 Move SW1 from PWR side to HW side, since it's HW parts.

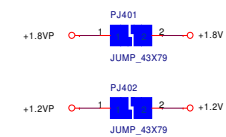
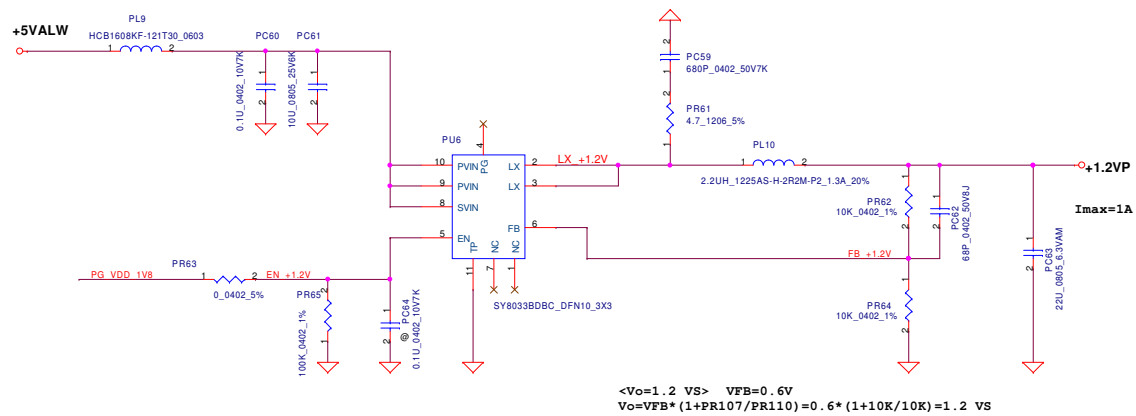
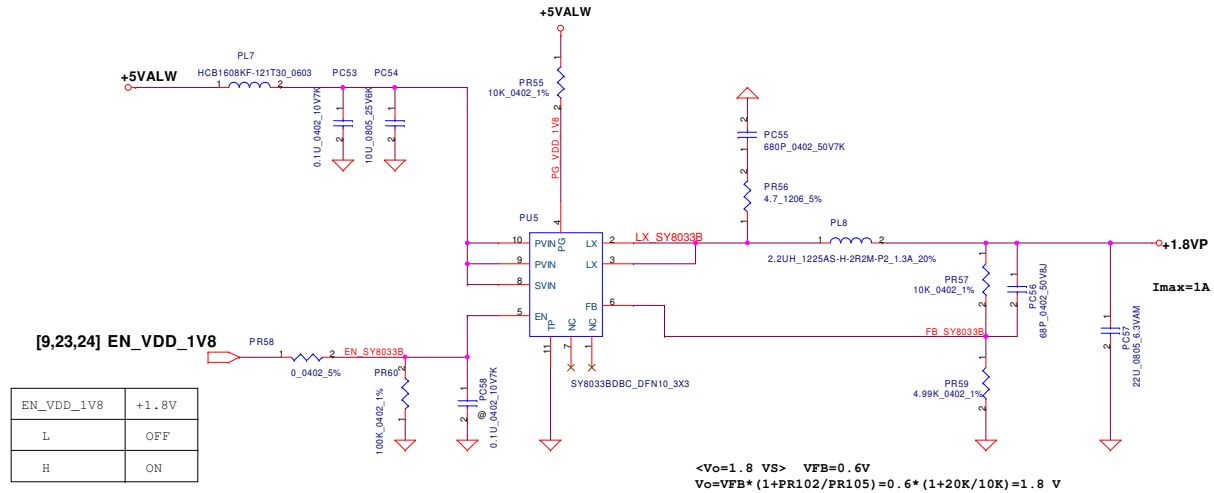


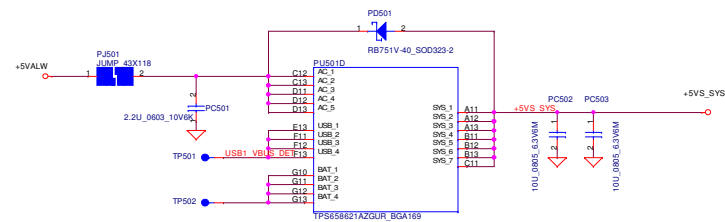
Security Classification	Compal Secret Data		Compal Electronics, Inc.	
Issued Date	2011/4/1	Deciphered Date	2010/12/01	Title
THIS SHEET OF ENGINEERING DRAWING IS THE PROPRIETARY PROPERTY OF COMPAL ELECTRONICS, INC. AND CONTAINS CONFIDENTIAL AND TRADE SECRET INFORMATION. THIS SHEET MAY NOT BE TRANSFERRED FROM THE CUSTODY OF THE COMPETENT DIVISION OF R&D DEPARTMENT EXCEPT AS AUTHORIZED BY COMPAL ELECTRONICS, INC. NEITHER THIS SHEET NOR THE INFORMATION IT CONTAINS MAY BE USED BY OR DISCLOSED TO ANY THIRD PARTY WITHOUT PRIOR WRITTEN CONSENT OF COMPAL ELECTRONICS, INC.				DC/DC/BUTTON
Size	C	Document Number	LA-7461P	Rev. 0.3
Date:	Monday, April 25, 2011	Sheet	24	of 35



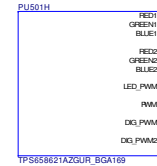
Security Classification		Compal Secret Data		Compal Electronics, Inc.	
Issued Date		2011/11/5		Deciphered Date	
2010/12/01		Title		BATTERY CONN.	
THIS SHEET OF ENGINEERING DRAWING IS THE PROPRIETARY PROPERTY OF COMPAL ELECTRONICS, INC. AND CONTAINS CONFIDENTIAL AND TRADE SECRET INFORMATION. THIS SHEET MAY NOT BE TRANSFERRED FROM THE CUSTODY OF THE COMPETENT DIVISION OF R&D DEPARTMENT EXCEPT AS AUTHORIZED BY COMPAL ELECTRONICS, INC. NEITHER THIS SHEET NOR THE INFORMATION IT CONTAINS MAY BE USED BY OR DISCLOSED TO ANY THIRD PARTY WITHOUT PRIOR WRITTEN CONSENT OF COMPAL ELECTRONICS, INC.		Size		Document Number	
C		LA-7461P		Rev.	
Date: Monday, April 25, 2011		Sheet		26 of 35	
1		2		3	



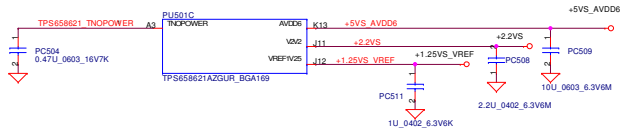




+VDD_SYS=5V
MAX current=1A

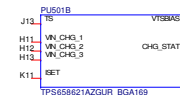


+VDD_AVDD6=5V
MAX current=0.01A

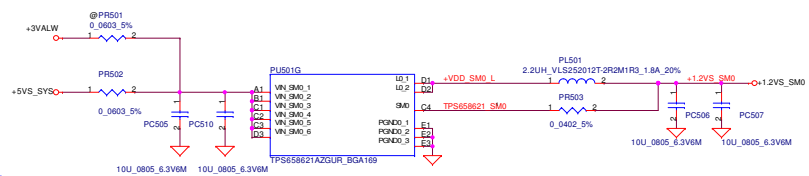


+VDD_V2V2=2.2V
MAX current=0.025A

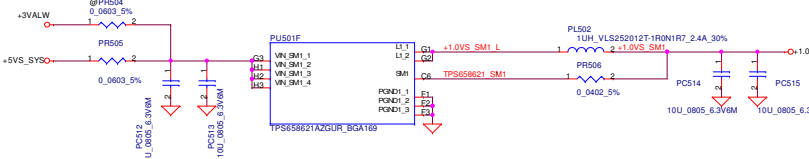
+VDD_VREF1V25 =1.25V
MAX current=0.01A



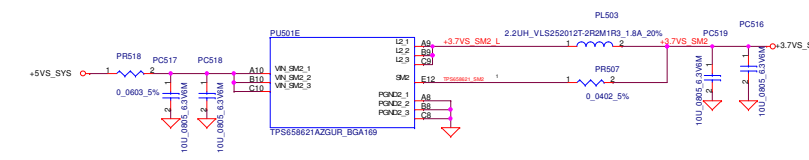
+VDD_SM0=1.2V
MAX current=0.6A



+VDD_SM1=1V
MAX current=1.5A



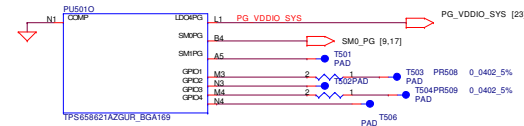
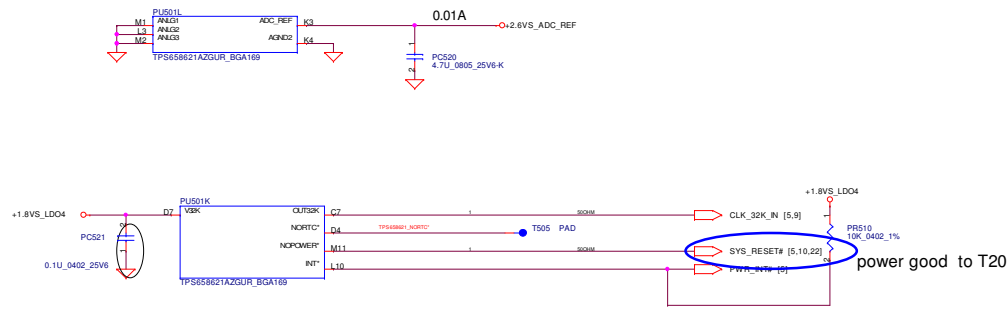
+VDD_SM2=3.7V
MAX current=0.75A



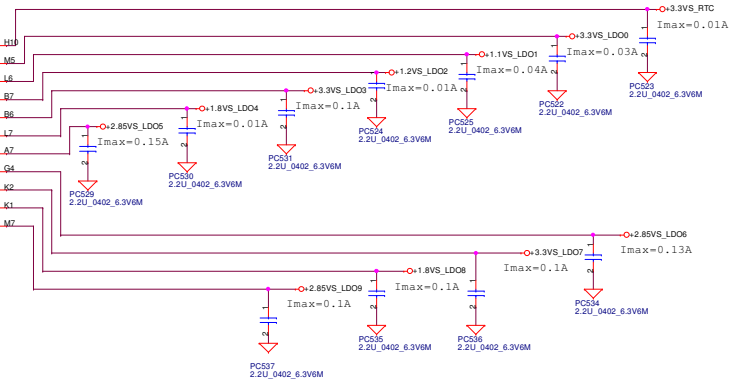
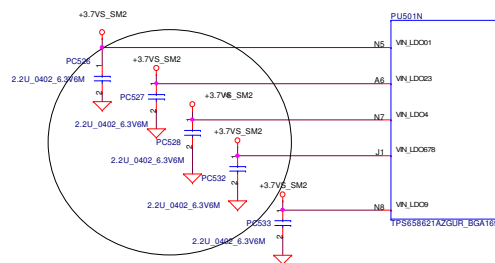
BOOST Converter

PMU #1

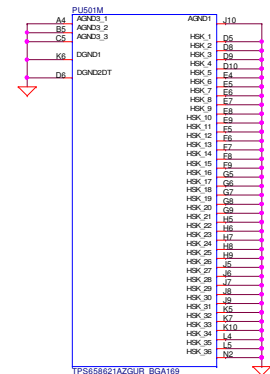
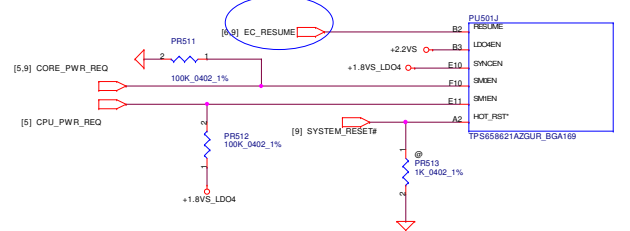
Security Classification	Compal Secret Data		Compal Electronics, Inc.	
Issued Date	2006/08/18	Deciphered Date	2008/09/20	Title
THIS SHEET OF ENGINEERING DRAWING IS THE PROPRIETARY PROPERTY OF COMPAL ELECTRONICS, INC. AND CONTAINS CONFIDENTIAL AND TRADE SECRET INFORMATION. THIS SHEET MAY NOT BE TRANSFERRED FROM THE CUSTODY OF THE COMPETENT DIVISION OF R&D DEPARTMENT EXCEPT AS AUTHORIZED BY COMPAL ELECTRONICS, INC. NEITHER THIS SHEET NOR THE INFORMATION IT CONTAINS MAY BE USED BY OR DISCLOSED TO ANY THIRD PARTY WITHOUT PRIOR WRITTEN CONSENT OF COMPAL ELECTRONICS, INC.				PMU#1
Size	Document Number	Rev	LA-7461P	
Quantity	Customer	0.2		
Date	Monday, April 25, 2011	Sheet	30	of 35



LAYOUT元件擺IC出PIN

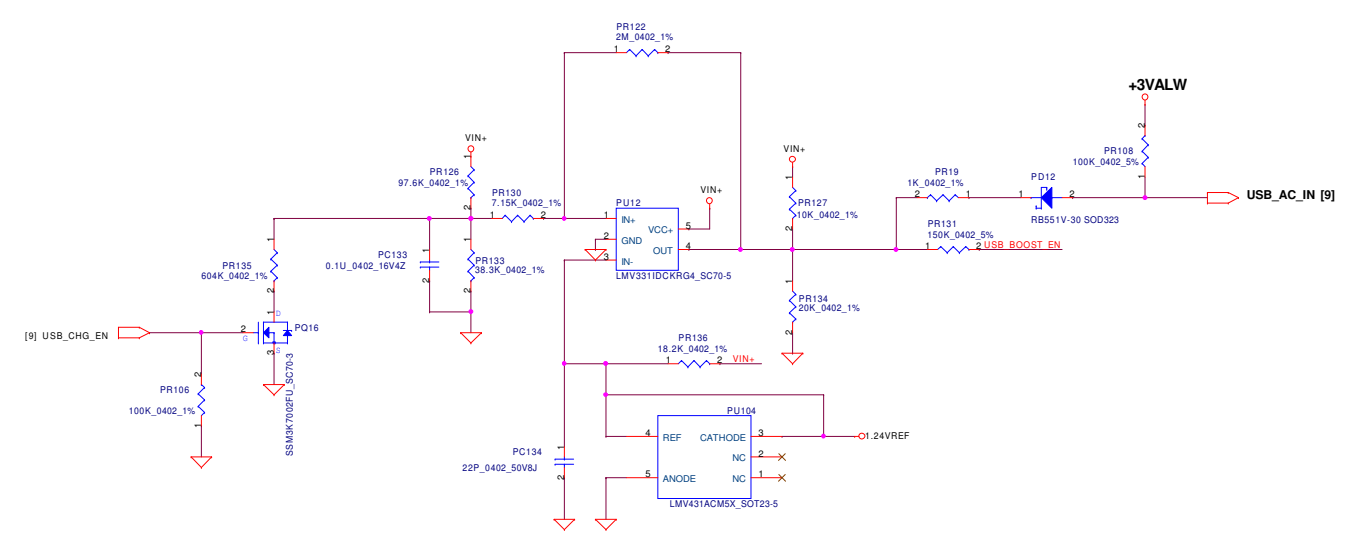
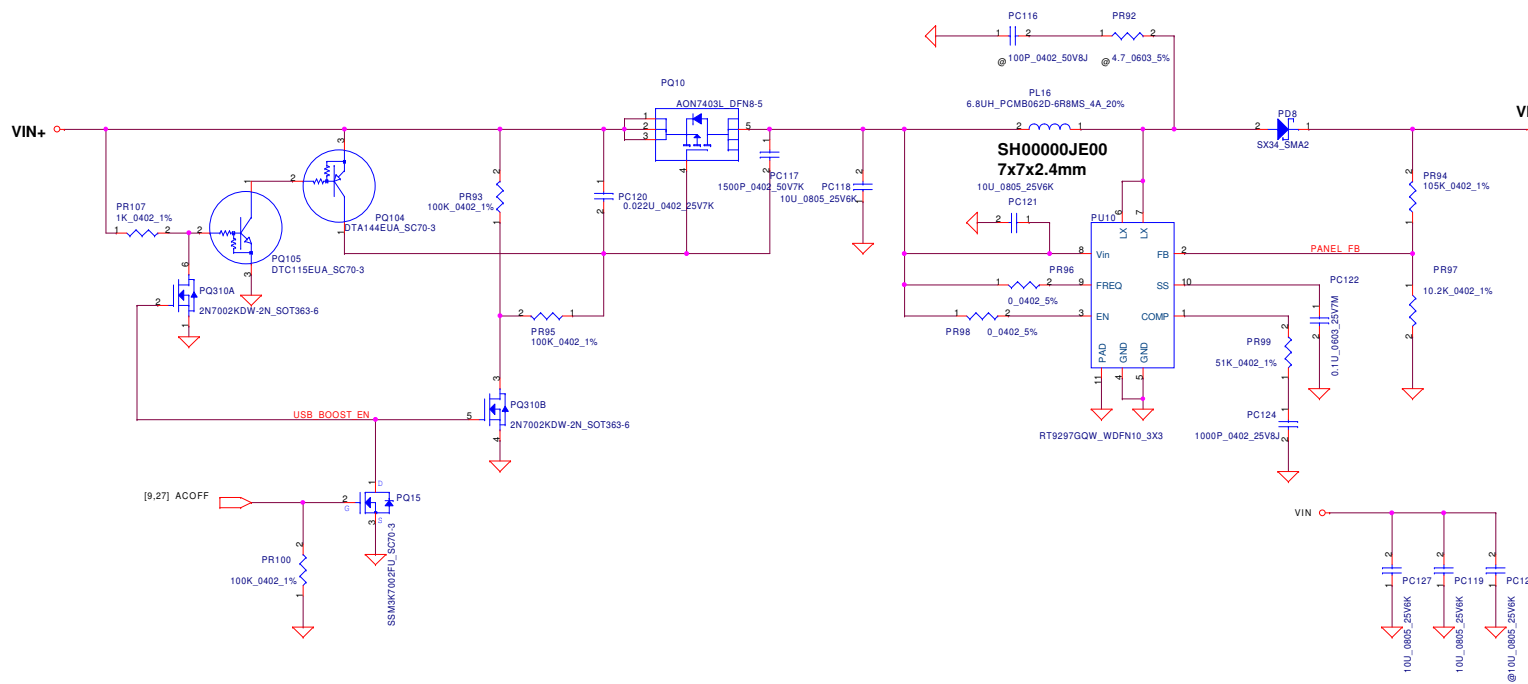


接到EC (POWER BUTTON)



PMU #2

Security Classification		Compal Secret Data		Compal Electronics, Inc.	
Issued Date	2006/08/18	Deciphered Date	2008/09/20	Title	
THIS SHEET OF ENGINEERING DRAWING IS THE PROPRIETARY PROPERTY OF COMPAL ELECTRONICS, INC. AND CONTAINS CONFIDENTIAL AND TRADE SECRET INFORMATION. THIS SHEET MAY NOT BE TRANSFERRED FROM THE CUSTODY OF THE COMPETENT DIVISION OF R&D DEPARTMENT EXCEPT AS AUTHORIZED BY COMPAL ELECTRONICS, INC. NEITHER THIS SHEET NOR THE INFORMATION IT CONTAINS MAY BE USED BY OR DISCLOSED TO ANY THIRD PARTY WITHOUT PRIOR WRITTEN CONSENT OF COMPAL ELECTRONICS, INC.				Size	Document Number
				Custom	LA-7461P
				Date	Monday, April 25, 2011
				Sheet	31 of 35



Version Change List (P. I. R. List) for Power Circuit

Page#	Title	Date	Request Owner	Issue Description	Solution Description
-------	-------	------	------------------	-------------------	----------------------

PHJ00 from SDV to FVT LA-7461P REV:0.1 -> 0.2 Modify <2011.01.30.~2011.03.08. >

Rev.	Item	Date	Impact	Page	Change Cause	Modify Description
0.2	1	1/31	CKT,Layout	7	-DFx suggest modify fiducial mark from two to three for M/B PCB bend test.	-Add FD5 and FD6
0.2	2	1/31	CKT,Layout	9	-Force recovery function always high issue when boot.	-Move SEARCH pin from EC pin 64 to pin 110, and add external pull high R398 to +3VALW.
0.2	3	1/31	CKT,Layout	11	-To solve EN_VDD_PNL turn on issue.	-Add C313 at Q19 G/D side.
0.2	4	1/31	CKT,Layout	12	-Internal SPK noise issue.	-Disconnect CDC_LEFT and CDC_LEFT#, and CDC_LEFT# connect to TP82.
0.2	5	1/31	CKT,Layout	18	-C284 interfere with shielding can.	-Change C284 package from 1206 to 0603.
0.2	6	1/31	CKT,Layout	11,18	-Update connector list from ME request.	-Modify JTS1 and JP5 footprint
0.2	7	1/31	CKT,Layout	7	-ME release newest drawing	-Add H13 and H14
0.2	8	2/9	CKT,Layout	12	-INT MIC can not record	-Delete C153 and C154, and change R191 and R192 to 0 ohms. MIC_LEFT_OUT pull high to +1.8VS, MIC_LEFT_OUT# pull down to AGND.
0.2	9	2/9	CKT,Layout	19	-Update connector list from ME request.	-Modify JCR1 footprint
0.2	10	2/9	CKT,Layout	9,24	-Add RED LED by customer request	-Add R399, R400, LED1, LED2, and Q22.Add SUSP_LED control signal from EC pin 34.
0.2	11	2/10	CKT,Layout	12	-Change HP and LINEOUT CR to GND by vendor request.	-Swap C275 and R193. Swap C276 and R203. Swap C131 and R168. Swap C132 and R169 by vendor request.
0.2	12	2/11	CKT,Layout	16	-BT can not work normally.	-Swap UART3_RXD and UART3_TXD, and swap UART3_RTS# and UART3_CTS# to solver BT cat not work normally.
0.2	13	2/14	CKT,Layout	18	-Power consumption measurement	-Add R410 for power consumption measurement.
0.2	14	2/15	CKT,Layout	13	-Cradle micro USB no function.	-Change JDOCK pin18 to +USB1_VBUS and serial R411 for solver Cradle micro USB no function issue.
0.2	15	2/15	CKT,Layout	16	-Vibrator can not work normally.	-Add 3V level GPIO 3VS_VIB_EN to control it, and reserve VIB_EN_T20.
0.2	16	2/15	CKT,Layout	11	-Follow sourcer's request to common design.	-Change U9 package from TSOP to BGA type.
0.2	17	2/15	CKT,Layout	11	-TSP pin define modify.	-Modify TSP JTS1 pin define by vendor request.
0.2	18	2/15	CKT,Layout	20	-Power consumption measurement	-Add R414 and R415 for power consumption measurement.
0.2	19	2/22	CKT,Layout	5,9	-Force recovery function abnormal issue	-Add level shift circuit (Q23, R416, and R417)between SEARCH pin and T20
0.2	20	2/22	CKT,Layout	20	-Follow RF's request	-Modify RF SW circuit by RF team request.
0.2	21	2/22	CKT,Layout	20	-Follow vendor's request	-Add 2P capacitance from CAP signal to GND for vnedor request.
0.2	22	2/23	CKT,Layout	11	-TSP SPI bus is 3V level	-Add level shift circuit (U34,U35,R235,R189,R204,C318,R427)
0.2	23	2/24	CKT,Layout	16	-+1.8VS leakage issue when WIFI enable	-Change pin 48 (VDDIO_SD) and pin 28 (VDDIO) from +3V_WLAN to +1.8V_WLAN.
0.2	24	2/24	CKT,Layout	16	-Follow vendor's request	-Swap DAP4_DOUT and DAP4_DIN signal
0.2	25	3/01	CKT,Layout	10	-Follow DFx's request.	-Add U37 for eMMC 14*18mm footprint by DFx request.
0.2	26	3/01	CKT,Layout	14	-Follow sourcer's request.	-Reserve U36 Thermal sensor.
0.2	27	3/01	CKT,Layout	24	-SW2 interfere with ME.	-Change debug power button SW2 to Top view type.
0.2	28	3/02	CKT,Layout	6,11	-Follow TSP vendor request.	-Modify TSP level shift circuit and add power switch.
0.2	29	3/02	CKT,Layout		-Power consumption measurement.	-Add R431,R432,R433. Change R104,R122,R121,R143,R144,R158,R159,R160,R161,R179,R220,R221,R223,R230,R231,R232,R233,R246,R410,R280 package to 0805.
0.2	30	3/02	CKT,Layout	17	-Follow customer request.	-Add JLTE1 and JLTE2 circuit by customer request.
0.2	31	3/03	CKT,Layout	9	-Double pull up.	-Delete R319 since SEARCH has double pull resistance.
0.2	32	3/03	CKT,Layout	8	-Modify Net name	-Modify LPDDR2 power net name.
0.2	33	3/03	CKT,Layout	9	-Prevent system hang up issue as PB/J30.	-KBC pin 13 add R436 100K ohms to GND.
0.2	34	3/04	CKT,Layout	12	-Follow vendor request.	-Change HP_AGND and LINE_AGND serial resistance to AGND. Connect HP_AGND to JHP1 pin5.
0.2	35	3/04	CKT,Layout	4,19	-SD Card no write protect function.	-Connect SDIO3_WP from U1_AE12 to JCR1 pin10. Delete R4. Add pull up resistance R439.
0.2	36	3/04	CKT,Layout	11	-Delete TSP debug connector JTS3.	-Delete JTS3 connector since the vendor can provide FFC cable.
0.2	37	3/06	CKT,Layout	13	-Cradle micro USB abnormally.	-Chage JDOCK1 pin 18 net name from +USB1_VBUS to +USB_CLIENT to solve Cradle micro USB can not work issue.
0.2	38	3/07	CKT,Layout	17	-Follow customer request.	-Add CNT1 to JWWAN1.3 and CNT2 to JWWAN1.5 for LTE function.
0.2	39	3/07	CKT,Layout	15	-Camera I2C bus level is 3.3V.	-Add CAM_I2C bus level shift circuit (Q26 ~ R440 ~ R441) to 3V level.
0.2	40	3/08	CKT,Layout	11	-Follow RF request	-Change C147,C148,C150,C152,C195,C196,C302,C303 from 10pF to 18pF by RF request.

PHJ00 from FVT to SIT LA-7461P REV:0.2 -> 0.3 Modify <2011.03.22.~2011.04.22. >

Rev.	Item	Date	Impact	Page	Change Cause	Modify Description
0.3	1	3/23	CKT,Layout	11	-Modify JTS1 pin define by follow vendor request.	-Swap JTS1 pin2 and pin3 to follow module pin define.
0.3	2	3/28	CKT,Layout	11	-C298 Material shortage	-Change C298 package from 0603 to 0805
0.3	3	3/28	CKT,Layout	13,19	-Follow NVidia request	-Add HDMI_DDC and HDMI_HPD level shift circuit (Q27 ~ Q28 ~ R444 ~ R445 ~ R446 ~ R447). Modify JDOCK1 pin 30 and 31 net name.
0.3	4	3/28	CKT	19	-Follow EMI request	-Change and instal R374 to 33ohms and C219 to 22pF by EMI request.
0.3	5	3/28	CKT	9	-X1 output CLK not accurate enough.	-Change C99 and C100 to 33pF by vendor suggestion.
0.3	6	4/13	CKT	17	-Follow SMSC USB3315 reference design	-Change R245 to 8.06K 1%
0.3	7	4/15	CKT	12	-SPK voice too small	-Change C149 to 3900pF by Audio team request.
0.3	8	4/13	CKT,Layout	19	-Avoid leakage issue.	-Change SDIO3_WP pull up level to +1.8VS
0.3	9	4/15	CKT	24	-BOM issue	-Move SW1 from PWR side to HW side.
0.3	10	4/15	CKT,Layout	9	-Power charger unstable issue.	-Add EC_ACIN by power and EC request.
0.3	11	4/15	CKT,Layout	6	-Power charger unstable issue.	-Change ACIN netname to ACIN_T20 by power request.
0.3	12	4/18	CKT,Layout	13,21	-Charger from Cradle micro USB issue.	-Add D33 and change +USB_CLIENT netname to +USB_CLIENT_DOCK to avoid charger from Cradle micro USB issue.
0.3	13	4/20	CKT,Layout	19	-Follow EMC request.	-Add ESD diode D34 for EMC request.
0.3	14	4/20	CKT,Layout	18	-Follow EMC request.	-Add C319,C320,C321,C322, and D35 by EMC request.
0.3	15	4/20	CKT,Layout	21	-Follow EMC request.	-Change D11,D12 to D36,D37 by EMC request.
0.3	16	4/20	CKT,Layout	14	-AKM eCompass shortage issue.	-Reserve Yamaha eCompass U38 by AKM eCompass shortage issue.
0.3	17	4/20	CKT,Layout	13	-Follow EMC request.	-Remove R341,R342, and install L29 by EMC request.
0.3	18	4/20	CKT	17	-Follow RF request.	-Change R242 and R244 to L30,L31 by RF request.
0.3	19	4/20	CKT	24	-Change LED to white light	-Change LED1 and LED2 from Red light to White light
0.3	20	4/21	CKT,Layout	12	-Follow EMC request.	-Add C323 and connector HP_AGND to D4
0.3	21	4/21	CKT,Layout	13	-Follow EMC request.	-Del ESD diode D6,D19,D20,D21,D22,D25,D31
0.3	22	4/20	CKT,Layout	17	-For ULPI PHY high speed test fail issue.	-Reserver X4,R449,R450,R451
0.3	23	4/20	CKT,Layout	13	-Follow EMC request.	-Modify JDOCK1.6 and JDOCK1.7 netname
0.3	24	4/20	CKT,Layout	19	-Follow NVidia reference design.	-Modify HDMI_DDC and HDMI_HPD level shift circuit. Change R444 and R445 to 1.8K. Change R273 and R274 to 2.2K. Add R448 HDMI_HPD pull down resistance.
0.3	25	4/20	CKT,Layout	21	-Follow EMC request.	-Change D36 and D37 to AZC099 by EMC request.

PHJ00 from FVT to SIT LA-7461P REV:0.2 -> 0.3 Modify <2011.03.22.~2011.04.25. >

[illegible]

Security Classification	Compal Secret Data			Compal Electronics, Inc.		
Issued Date	2011/11/5	Deciphered Date	2010/12/01	Title	HW_PIR2	
THIS SHEET OF ENGINEERING DRAWING IS THE PROPRIETARY PROPERTY OF COMPAL ELECTRONICS, INC. AND CONTAINS CONFIDENTIAL AND/OR SECRET INFORMATION. THIS SHEET MAY NOT BE TRANSFERRED FROM THE CUSTODY OF THE COMPETENT DIVISION OF R&D DEPARTMENT EXCEPT AS AUTHORIZED BY COMPAL ELECTRONICS, INC. NEITHER THIS SHEET NOR THE INFORMATION IT CONTAINS MAY BE USED BY OR DISCLOSED TO ANY THIRD PARTY WITHOUT PRIOR WRITTEN CONSENT OF COMPAL ELECTRONICS, INC.				Size	Document Number	Rev
				LA-7461P		
				Date:	Monday, April 25, 2011	Sheet